

FIG. 1

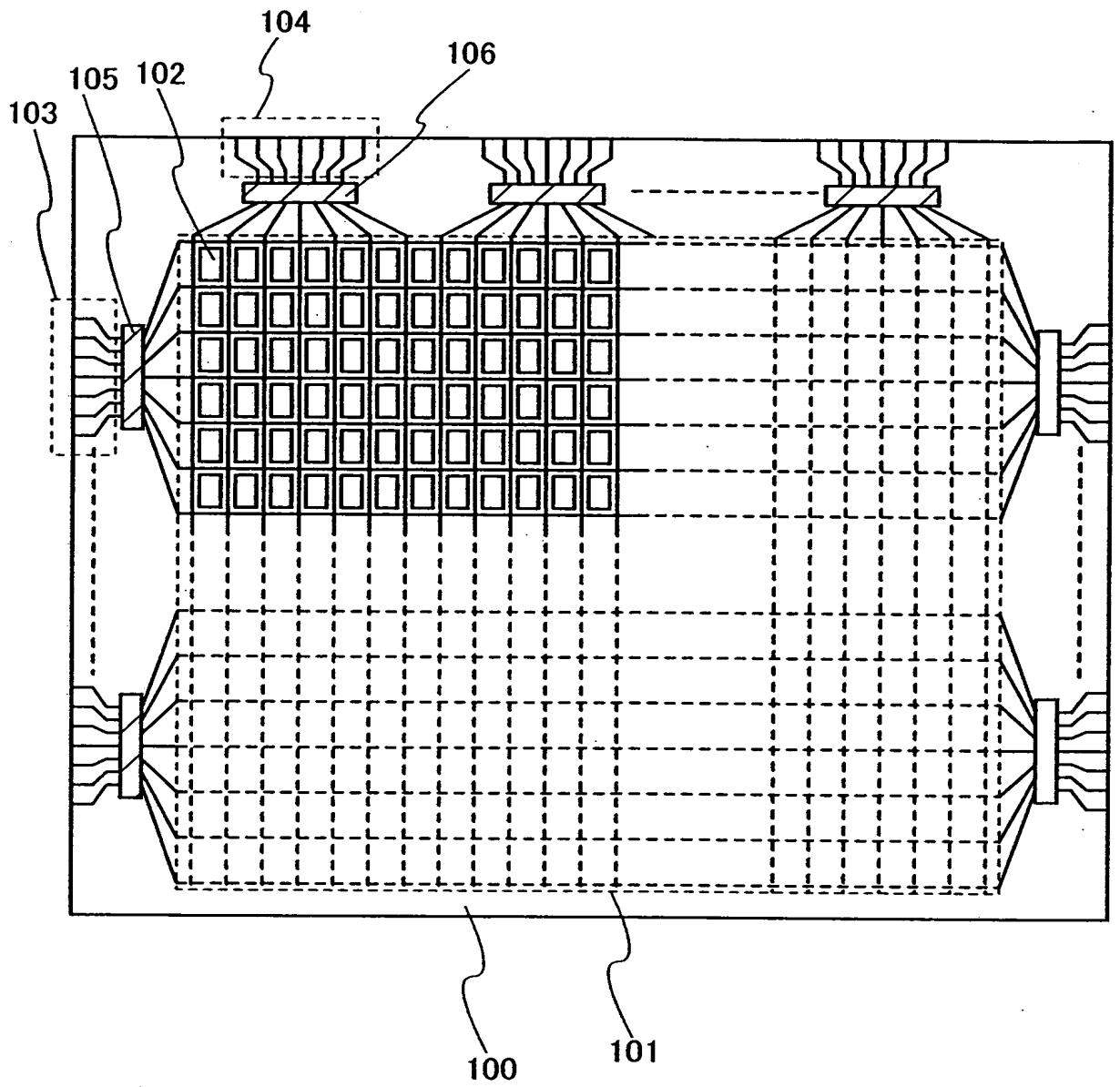


FIG. 2

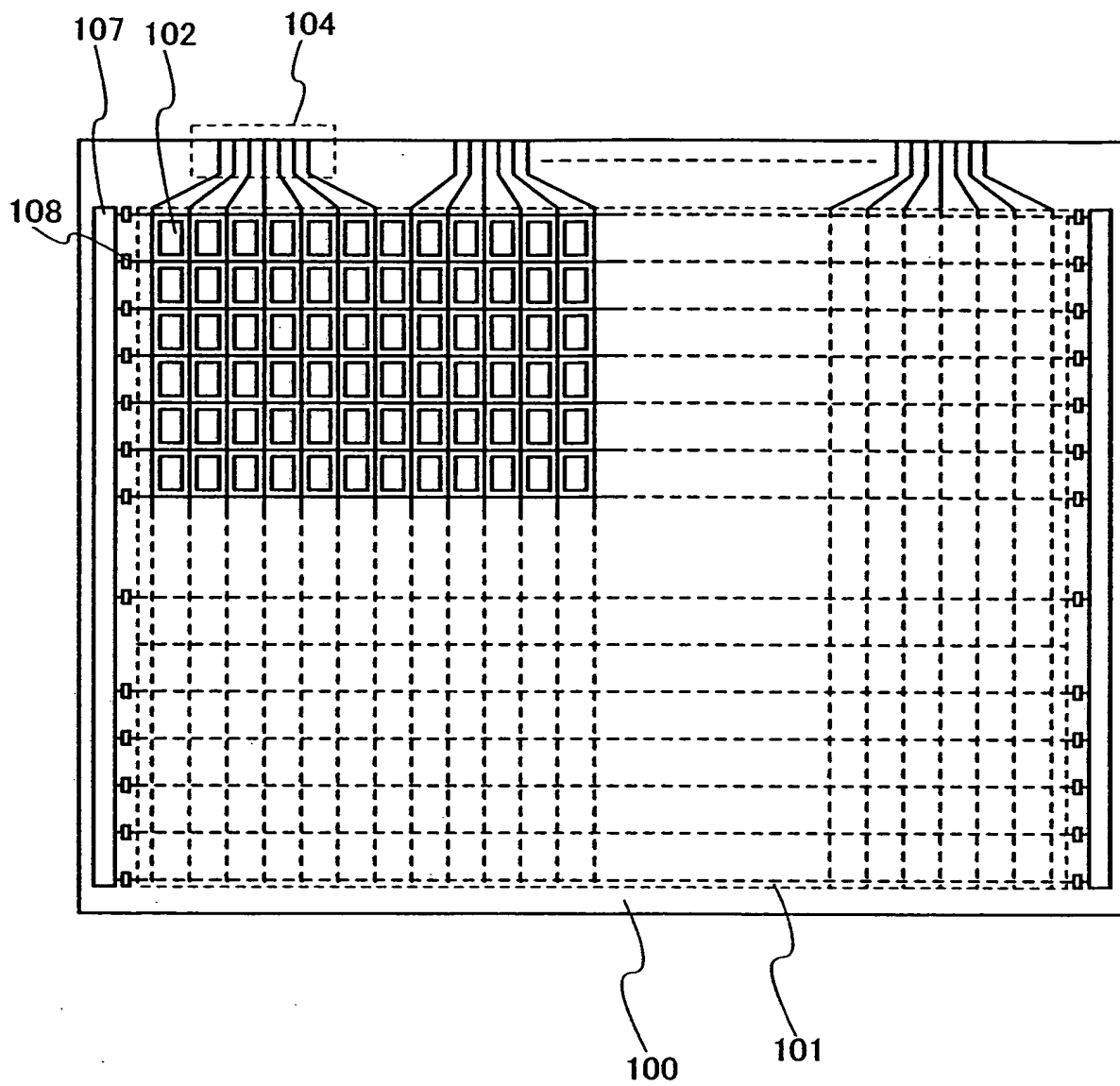


FIG. 3

FIG. 4A

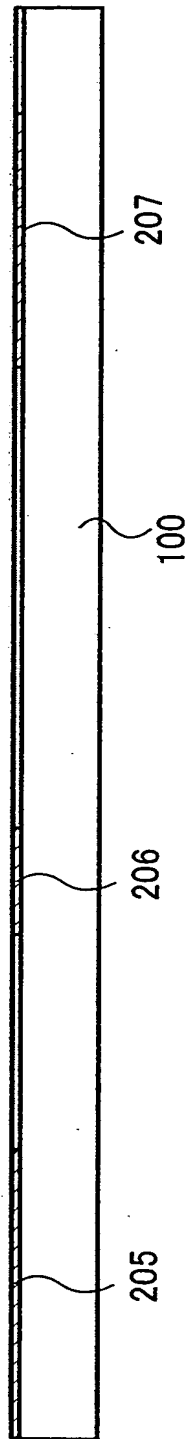


FIG. 4B

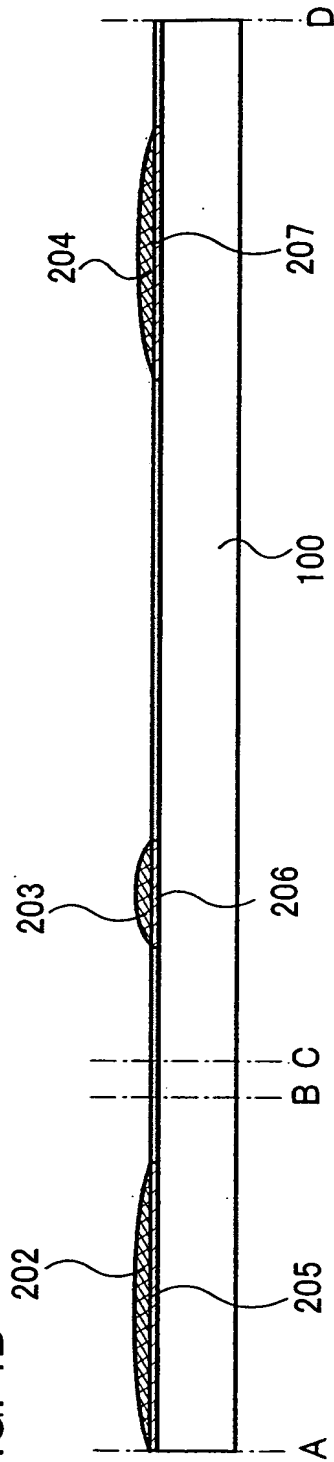


FIG. 4C

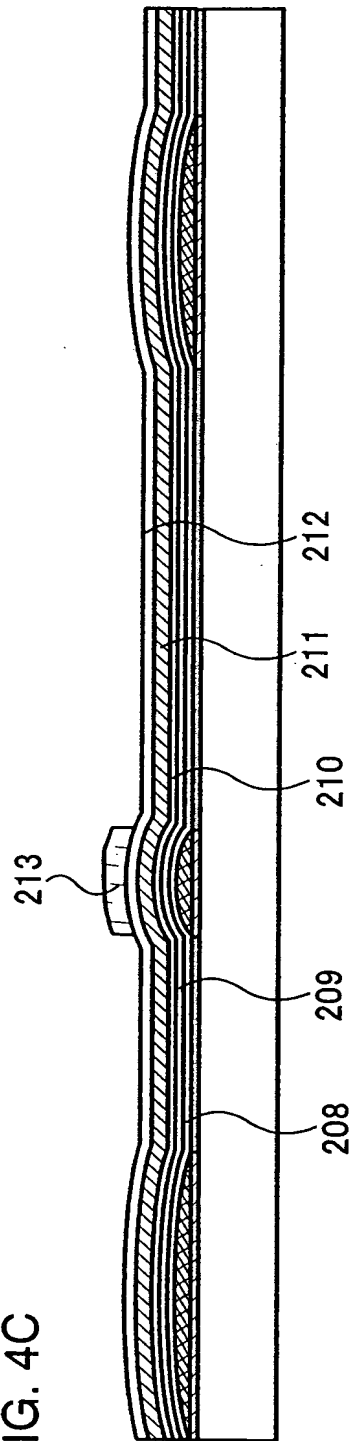


FIG. 5A

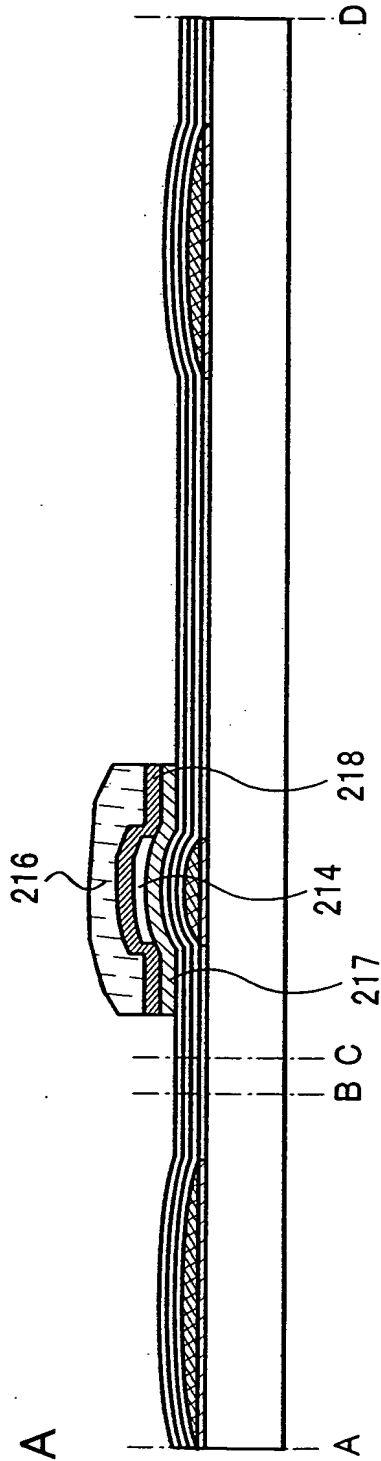


FIG. 5B

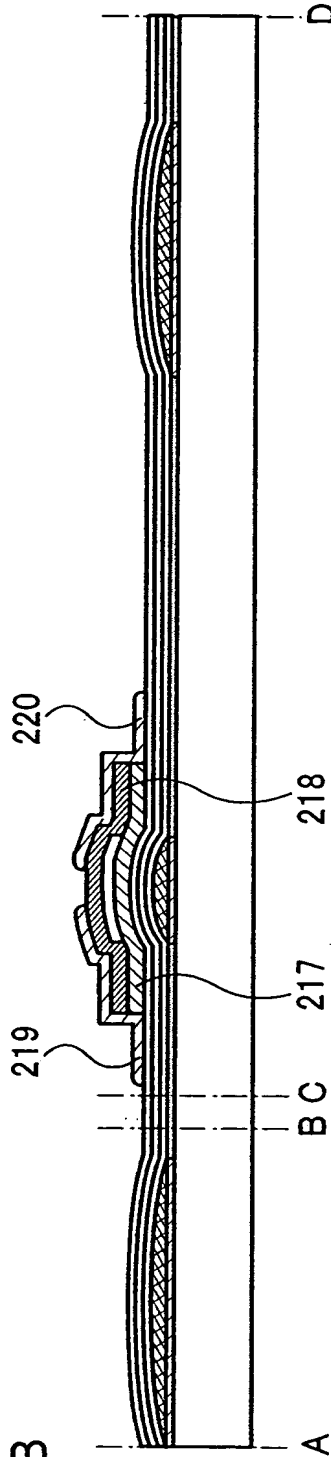


FIG. 5C

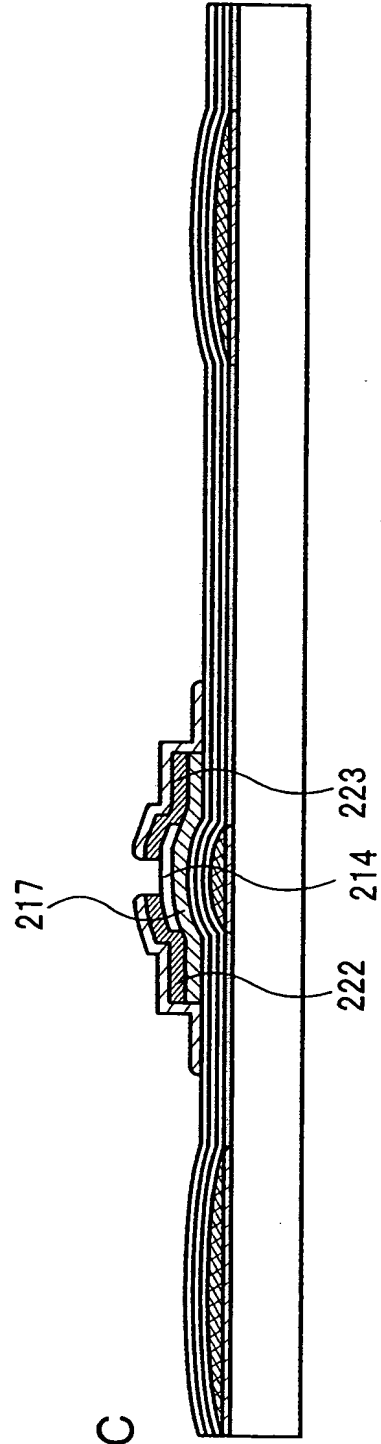


FIG. 6A

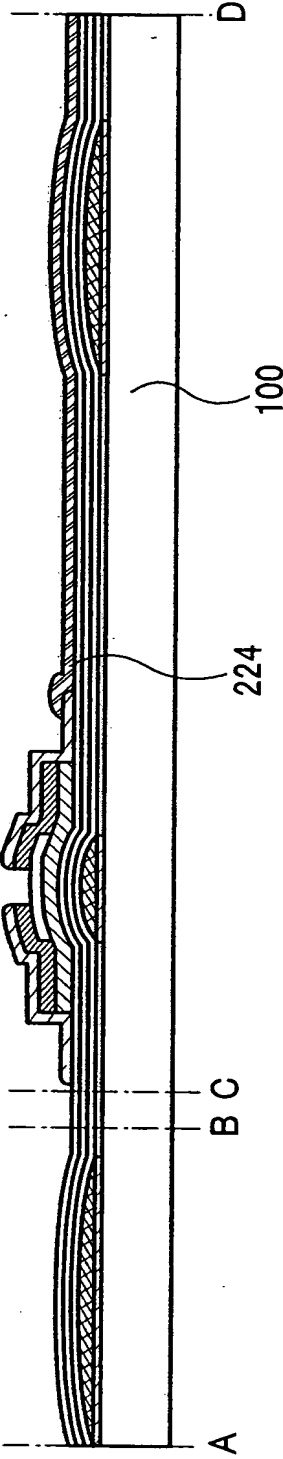


FIG. 6B

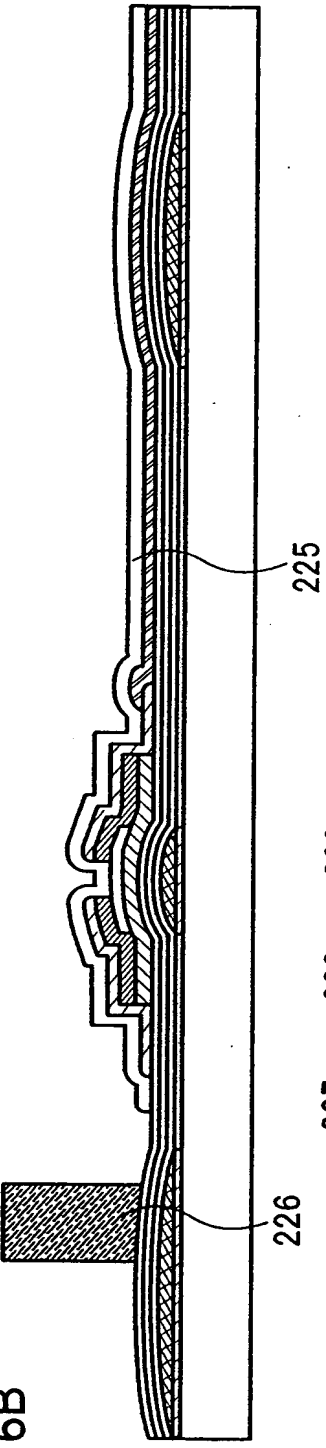
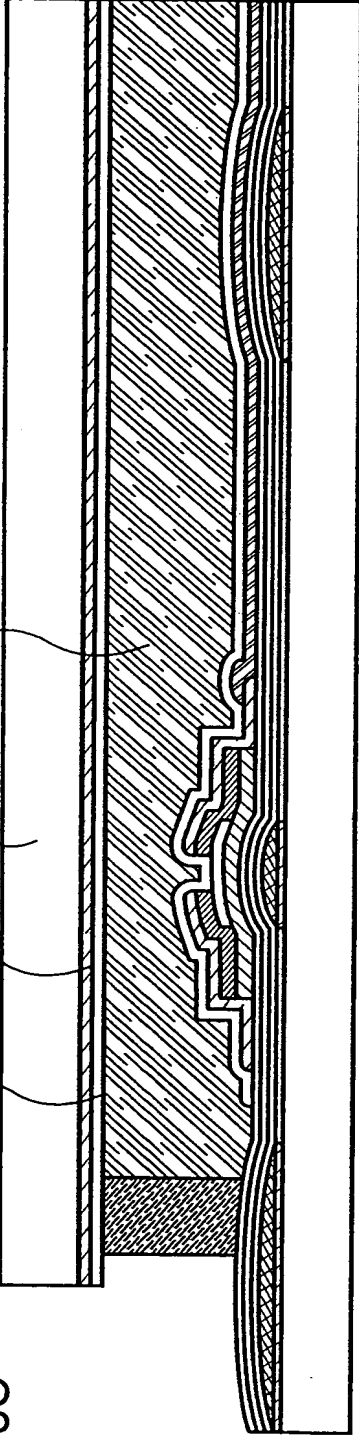


FIG. 6C



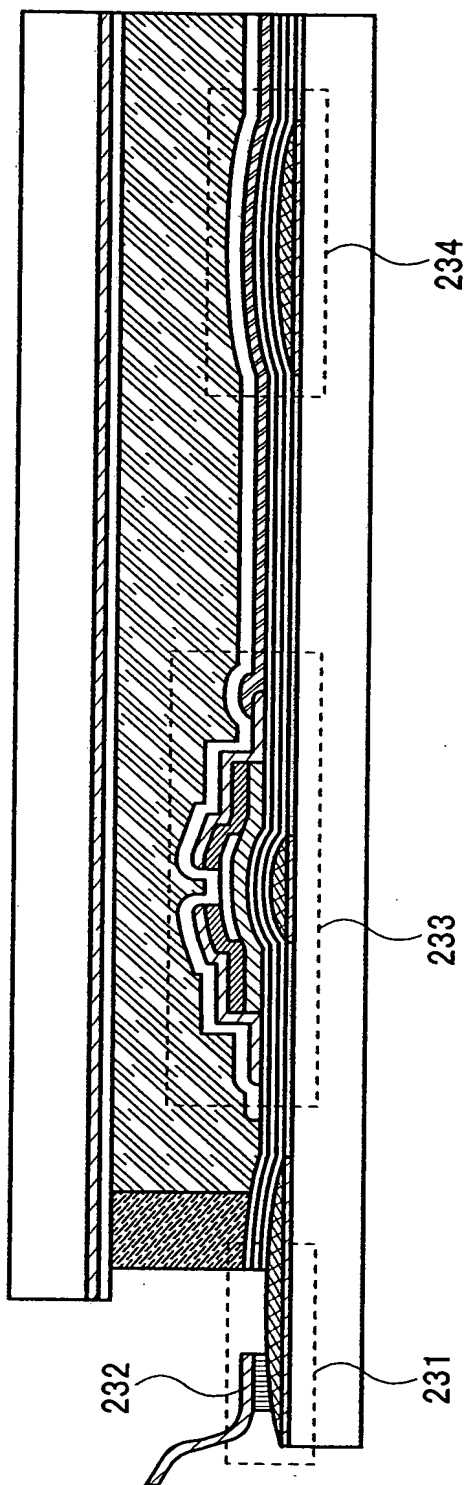


FIG. 7

FIG. 8A

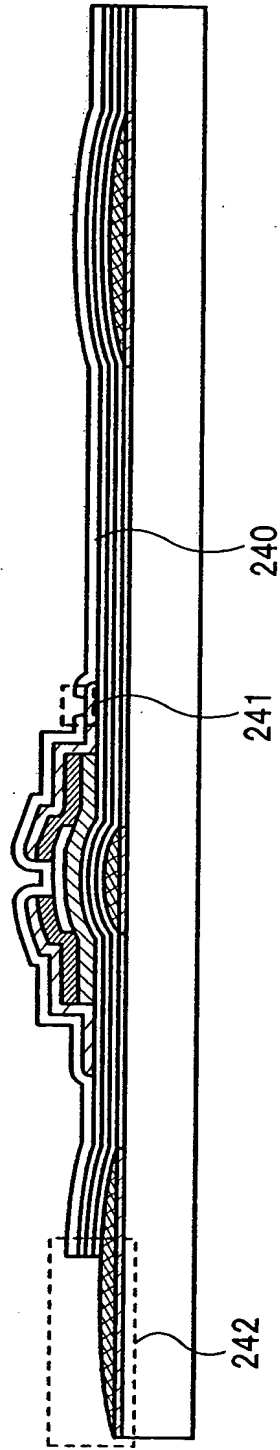
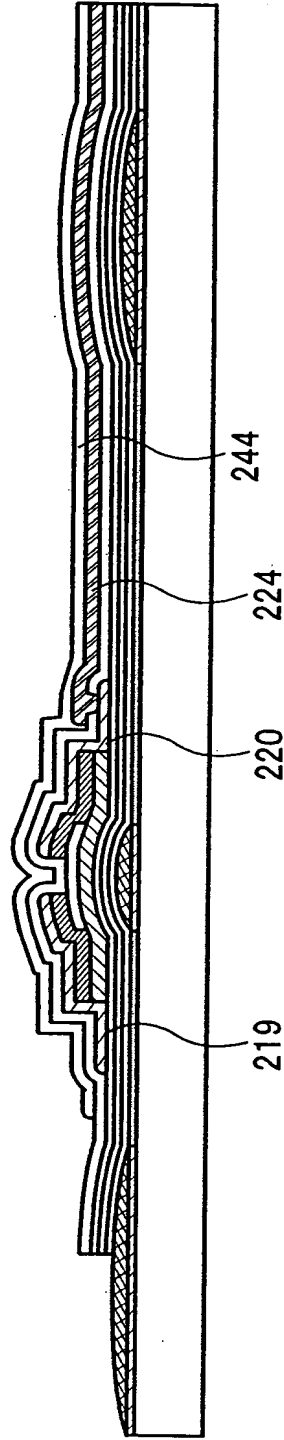


FIG. 8B



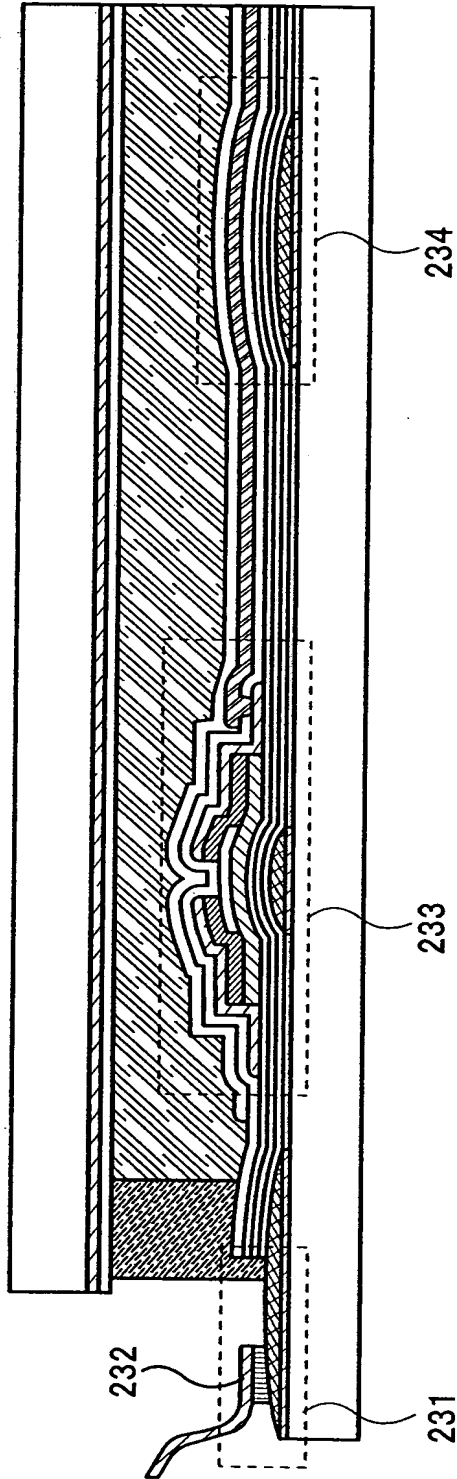
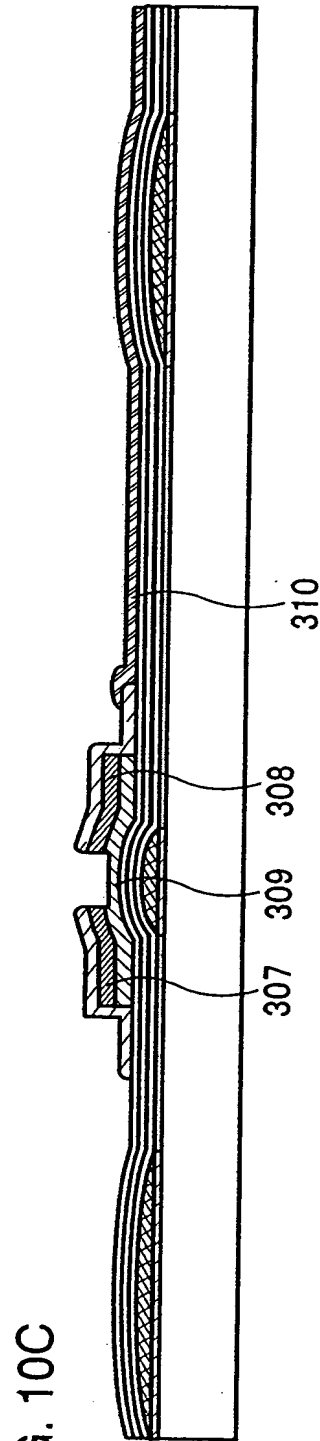
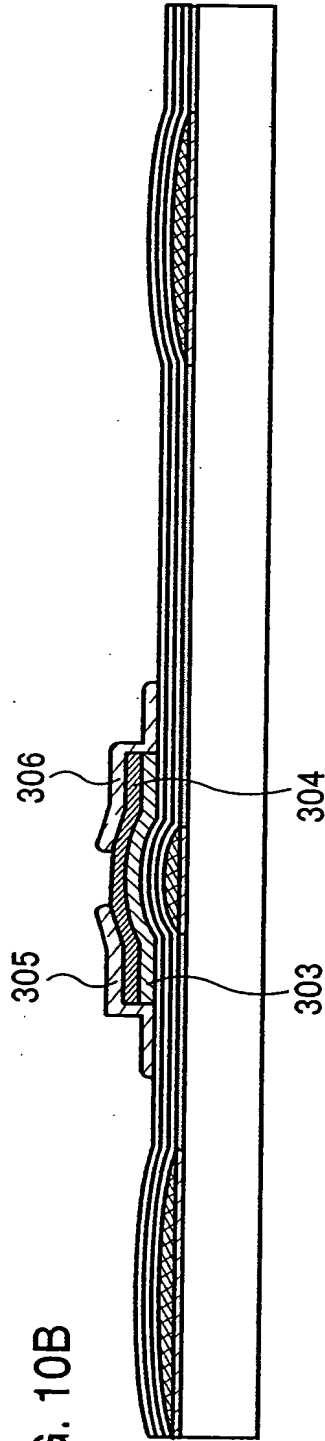
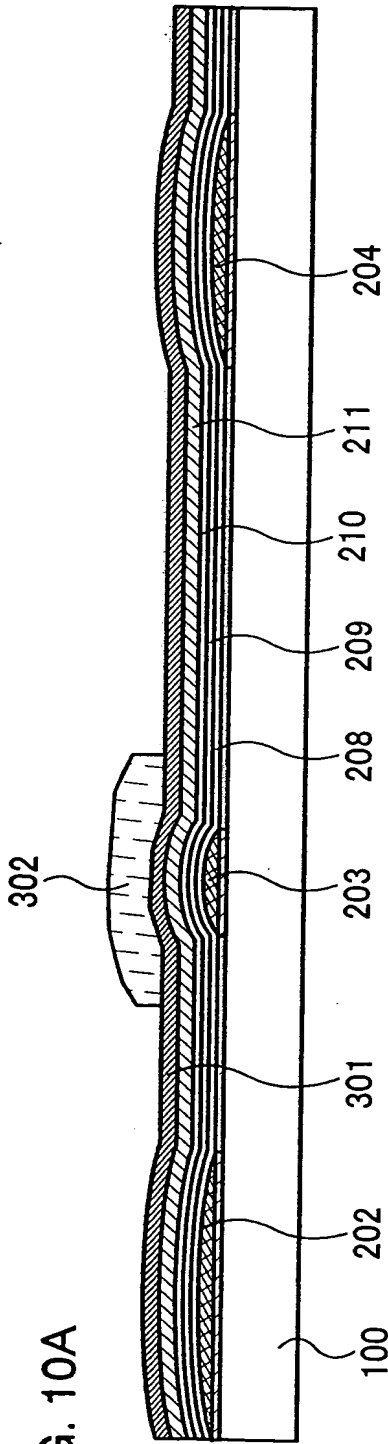


FIG. 9



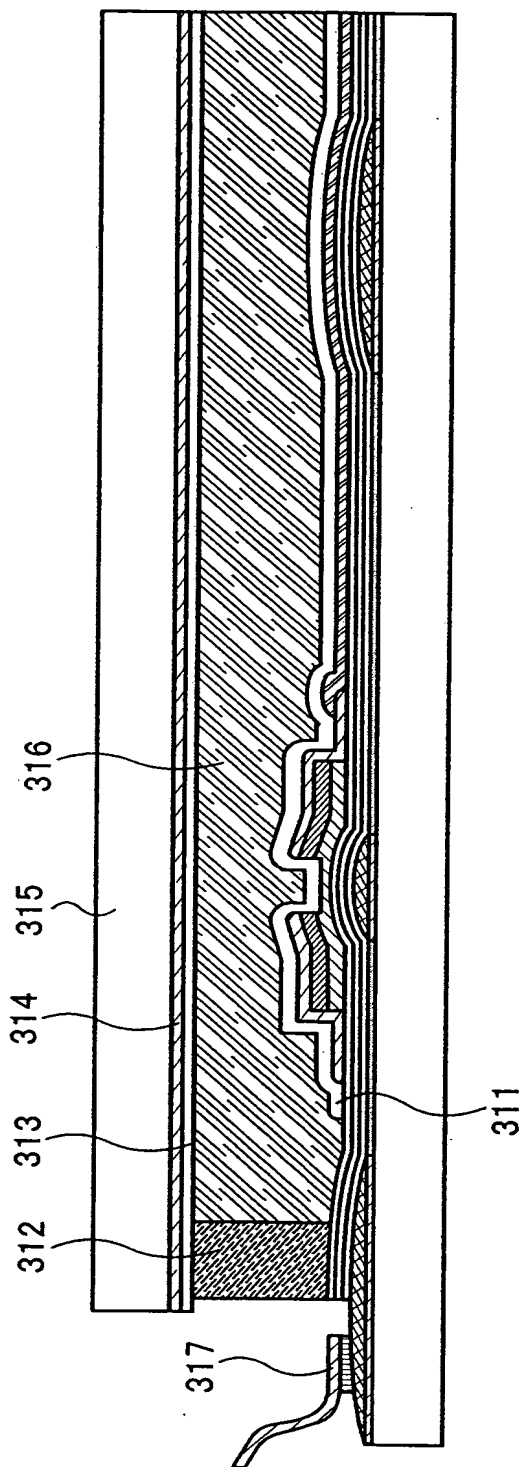


FIG. 11

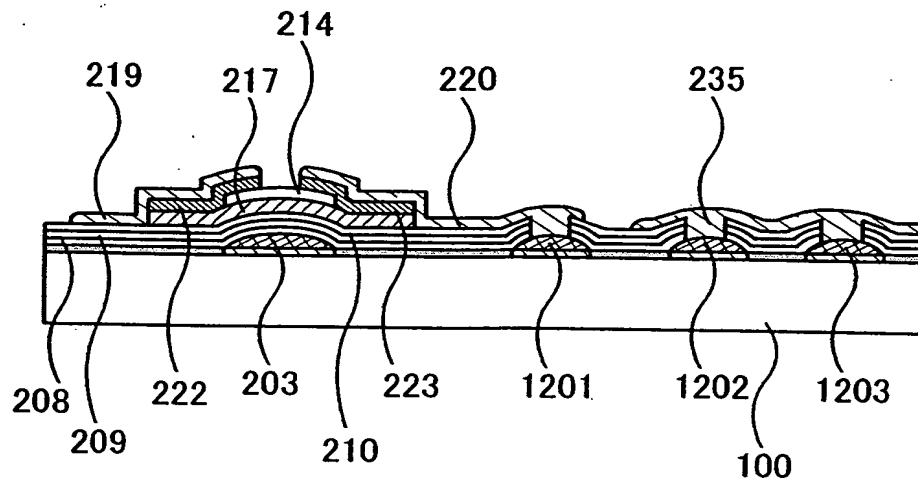


FIG. 12

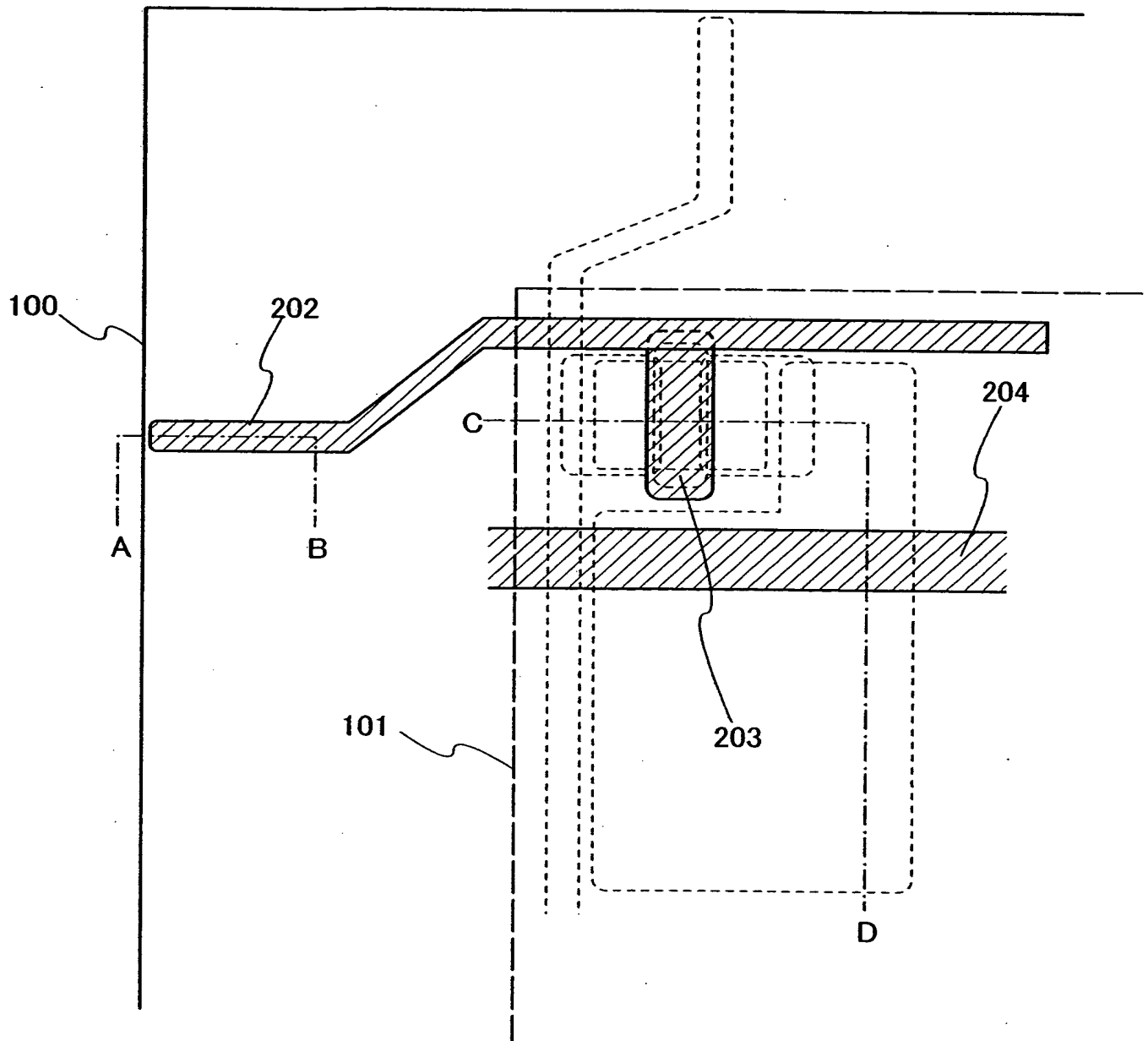


FIG. 13

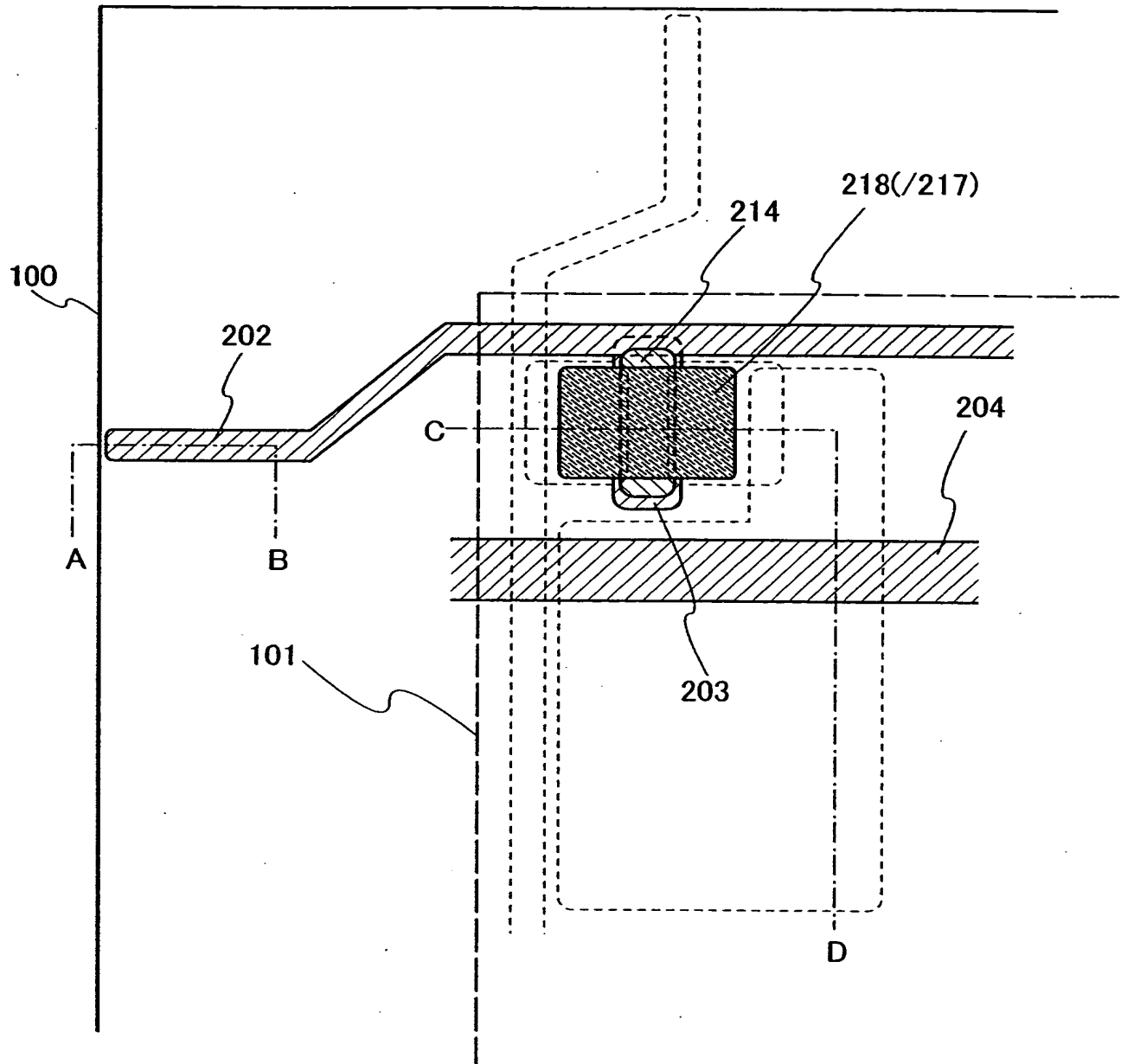


FIG. 14

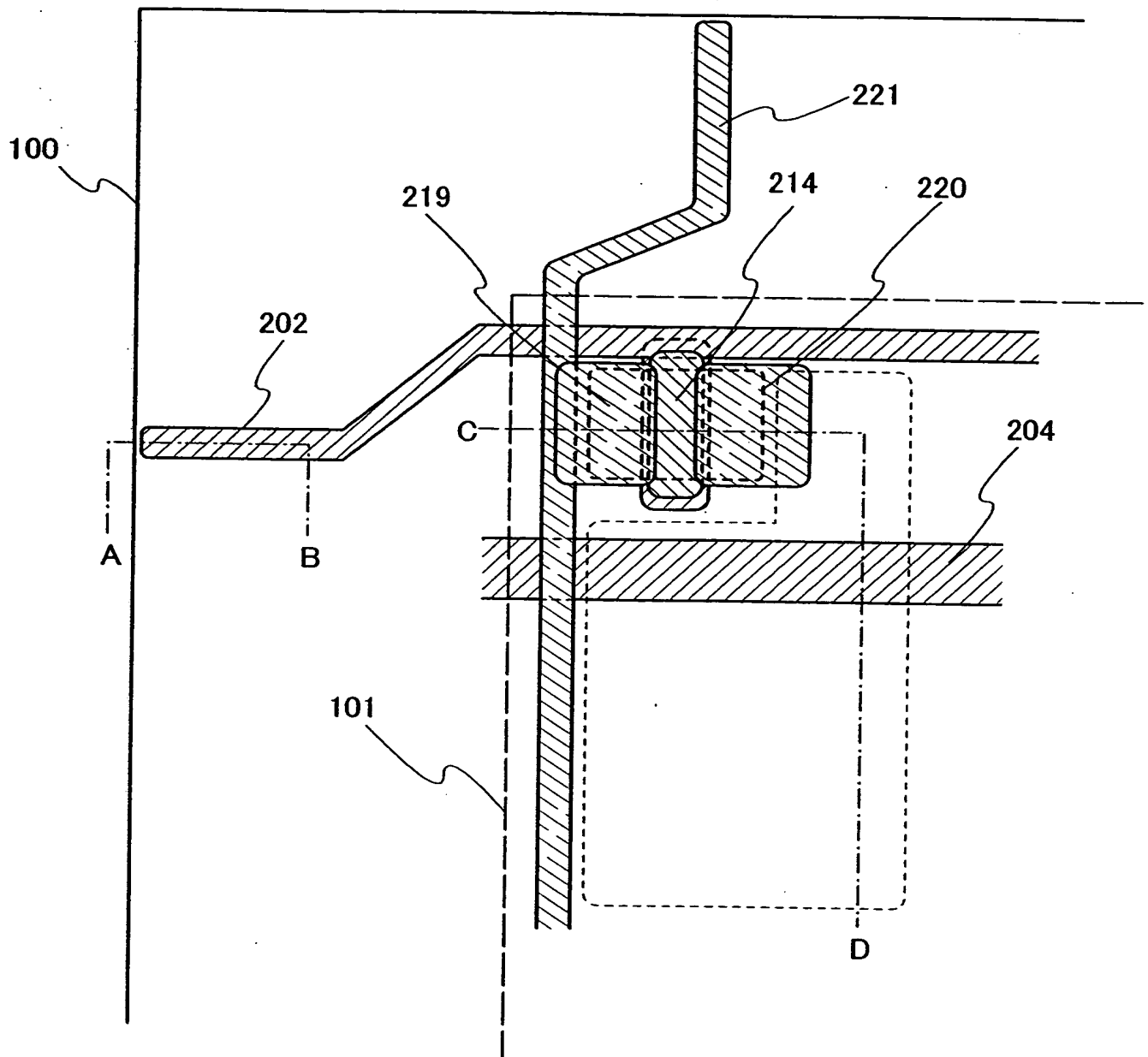


FIG. 15

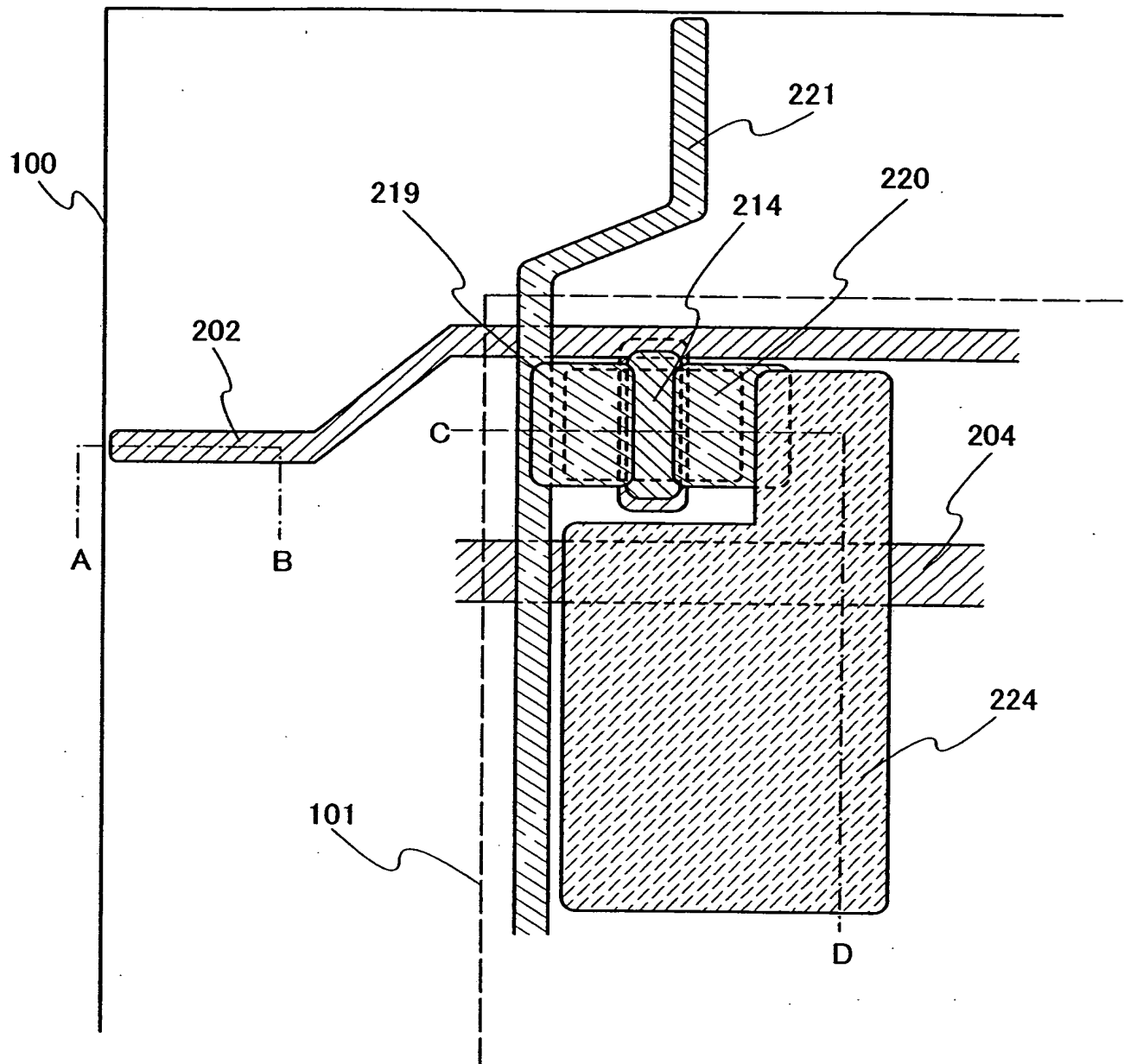


FIG. 16

FIG. 17A

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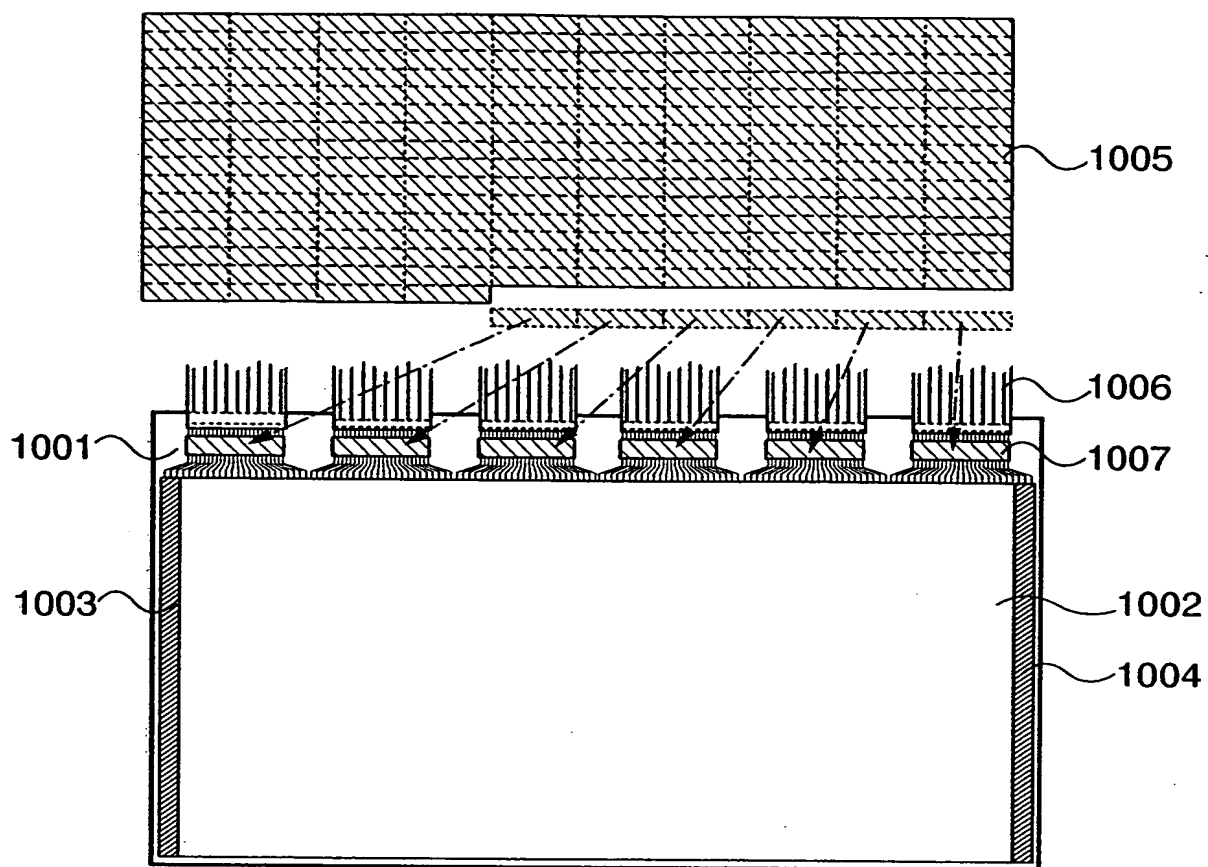


FIG. 17B

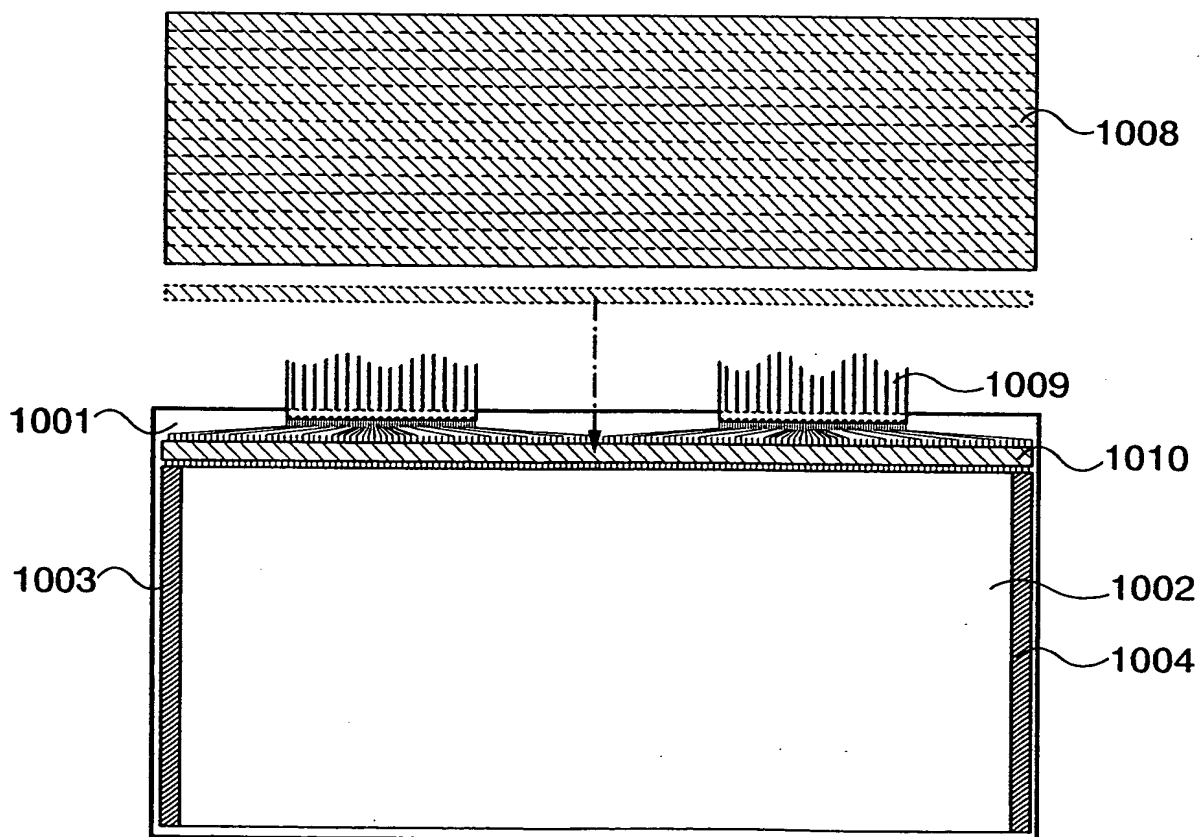


FIG. 18A

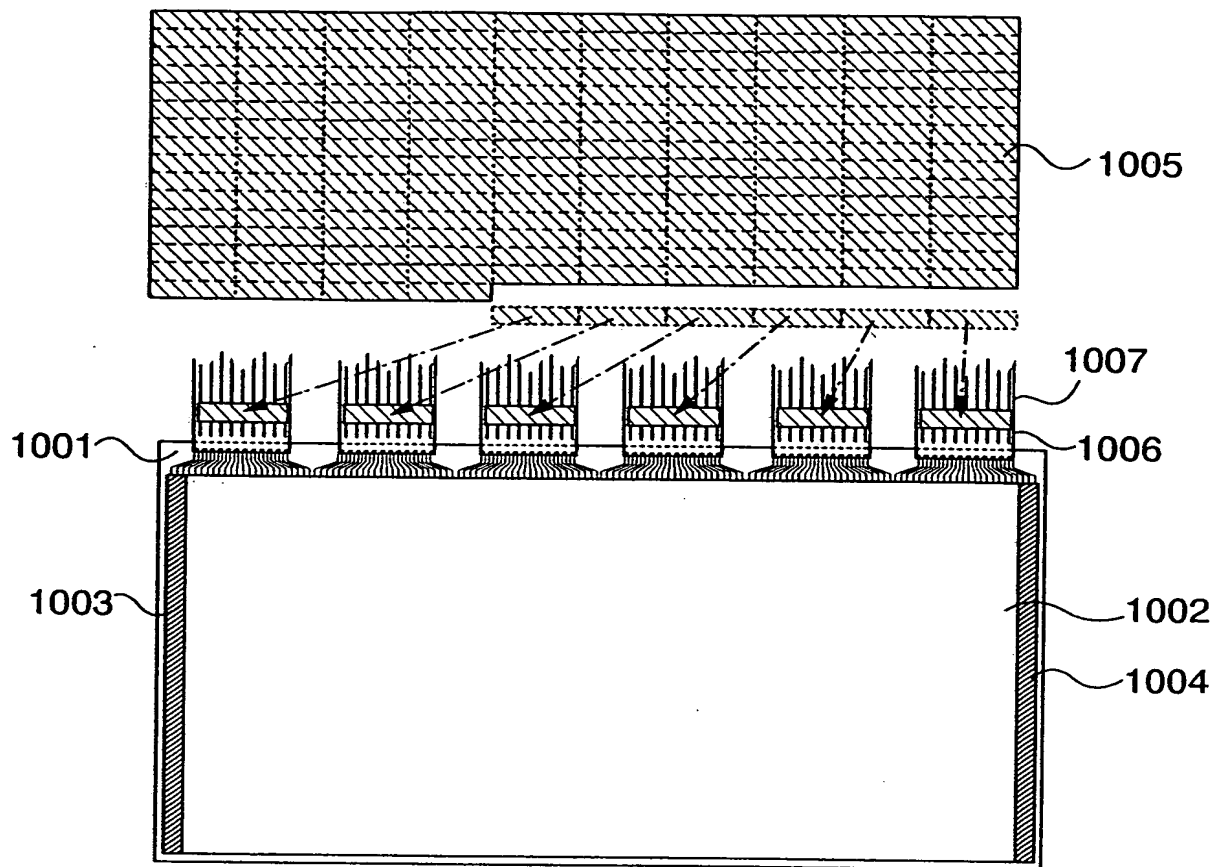


FIG. 18B

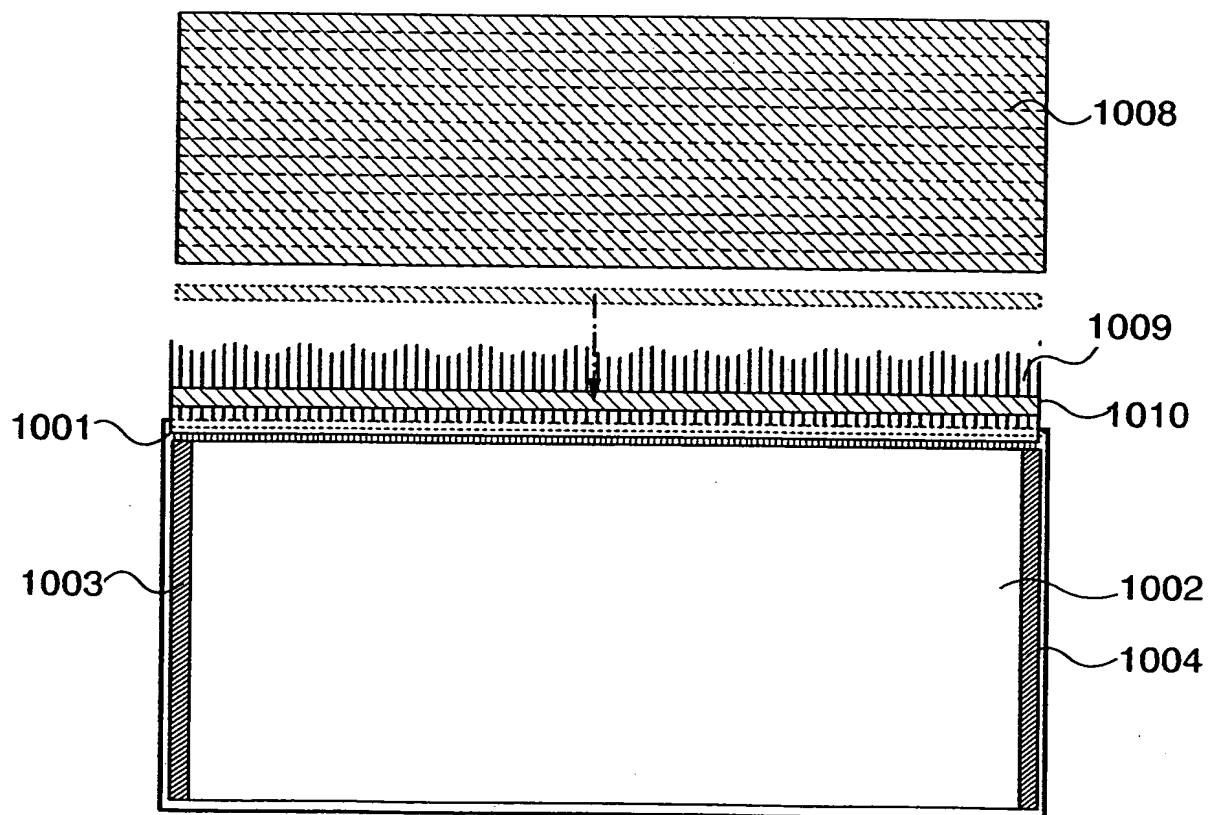


FIG. 19A

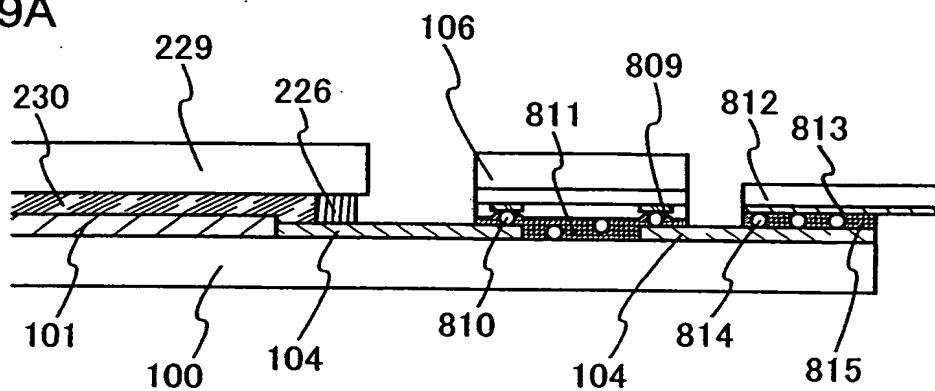
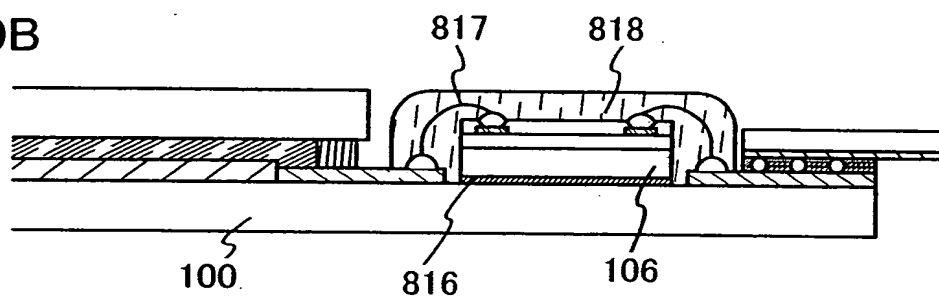


FIG. 19B



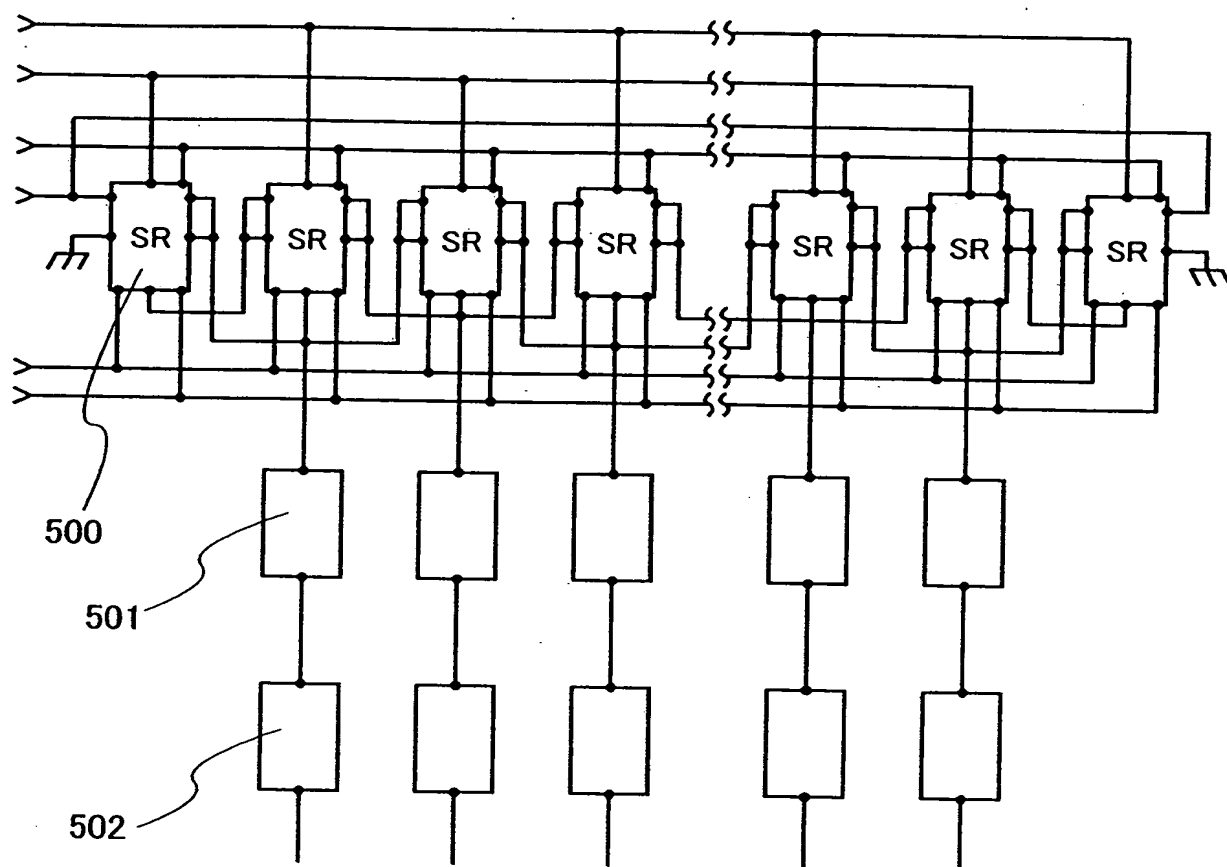


FIG. 20

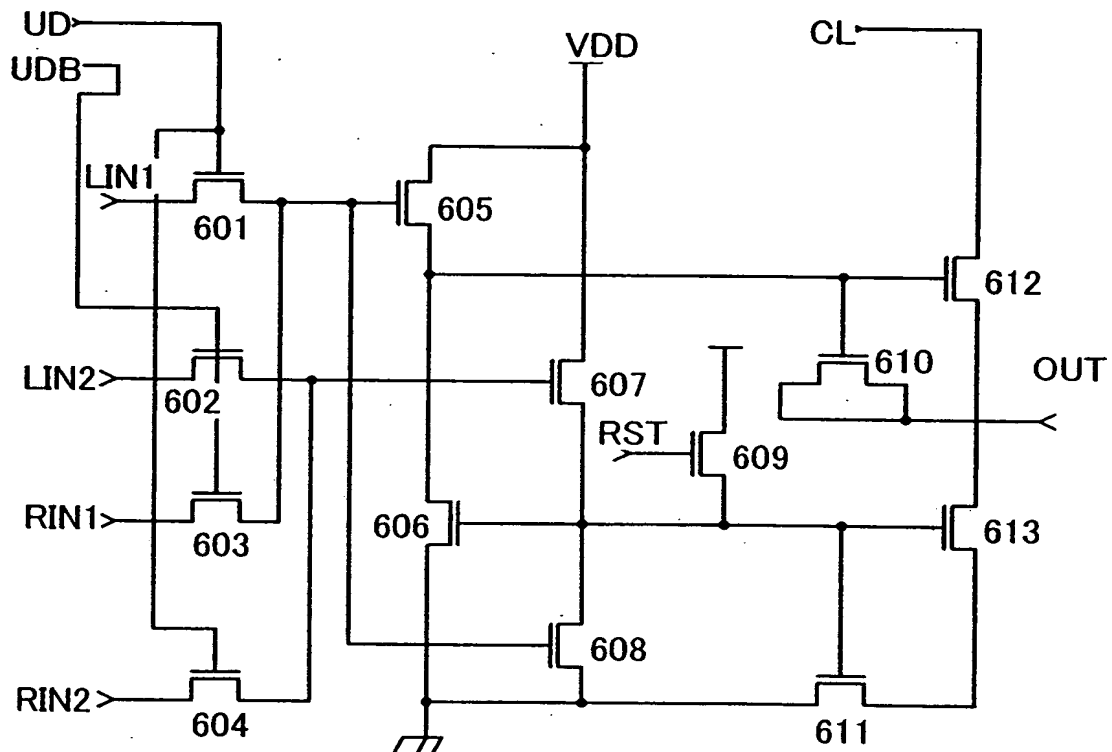


FIG. 21

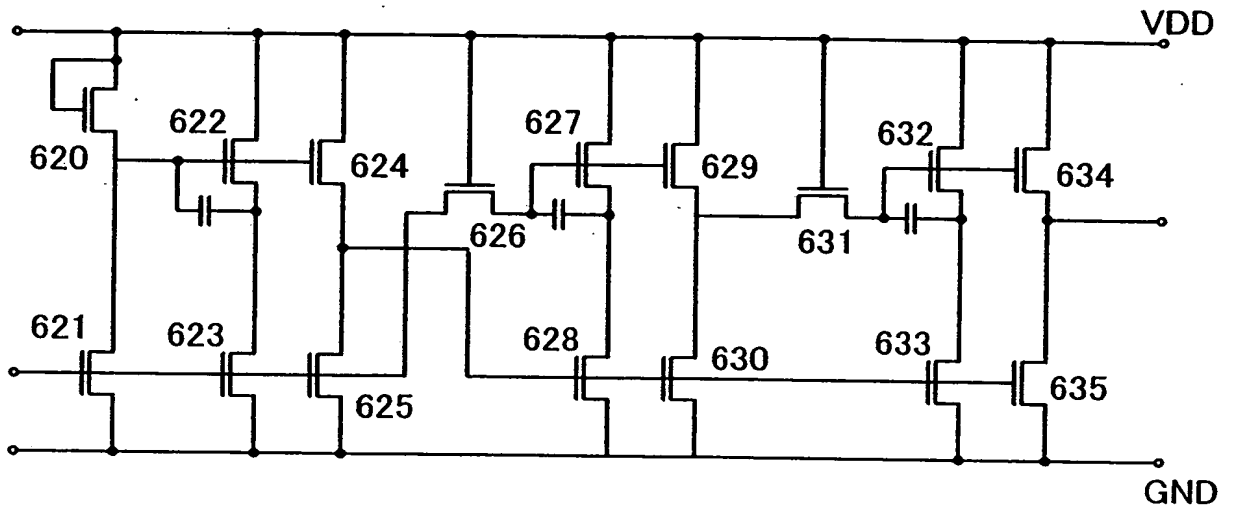


FIG. 22

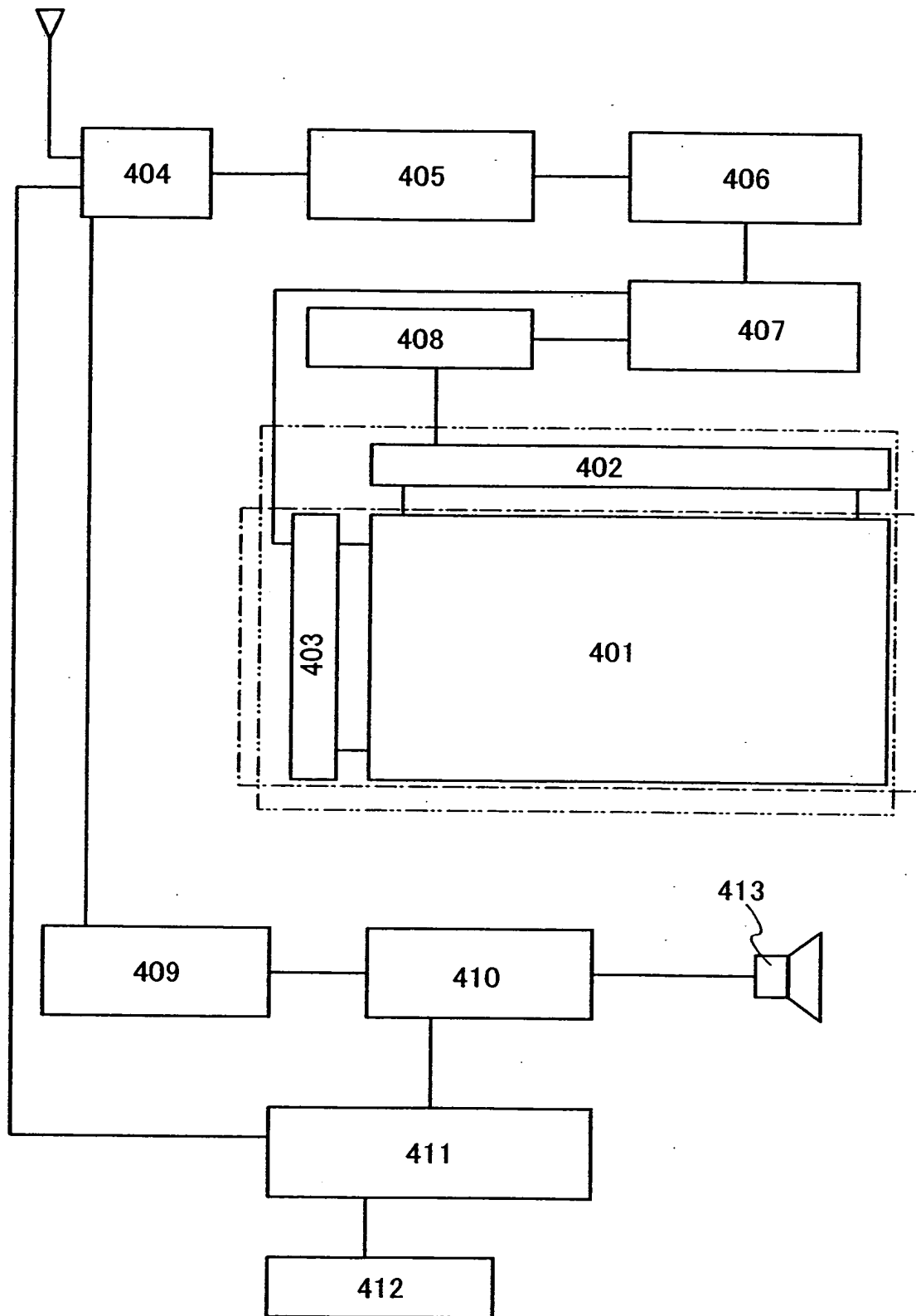


FIG. 23

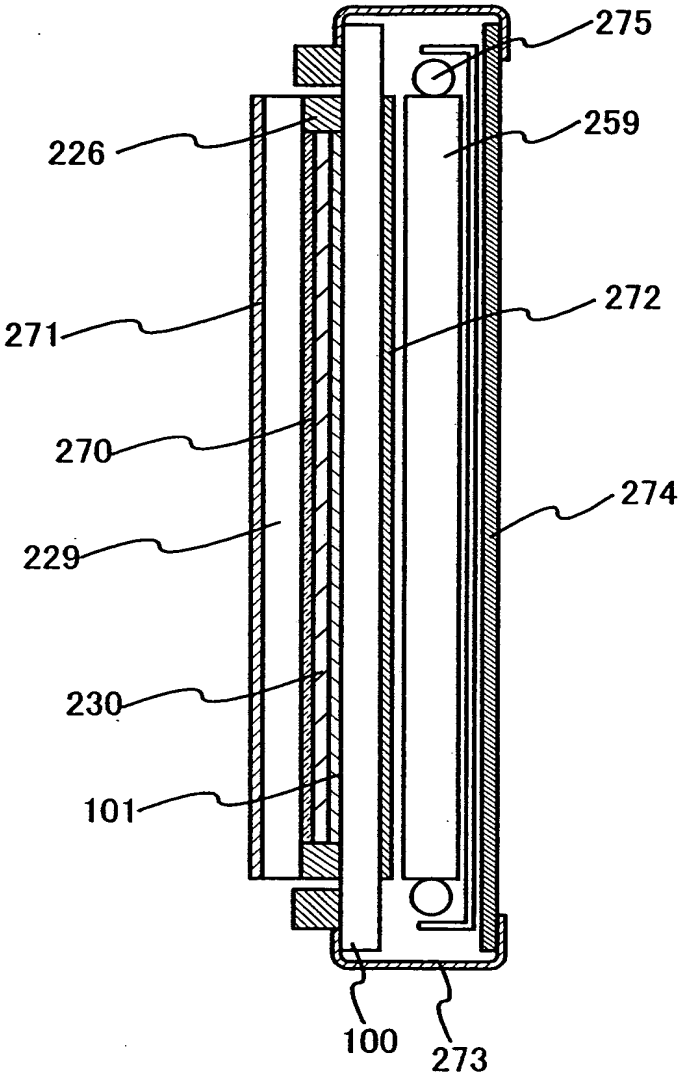


FIG. 24

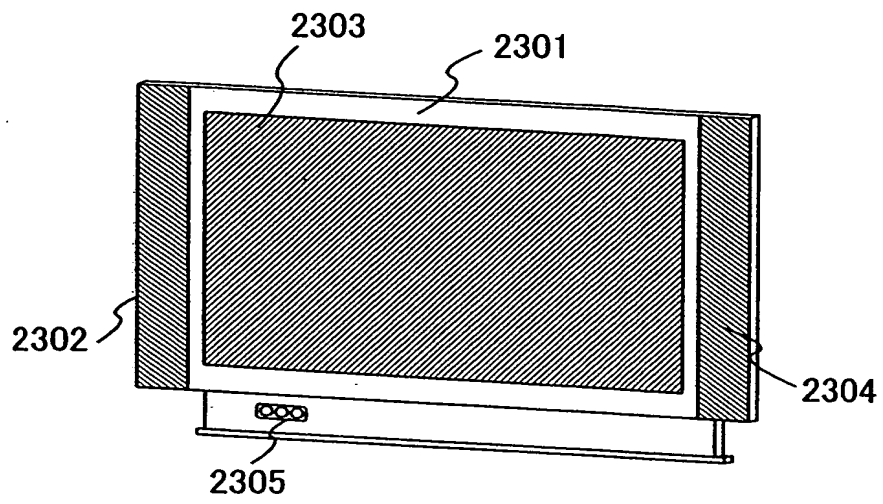
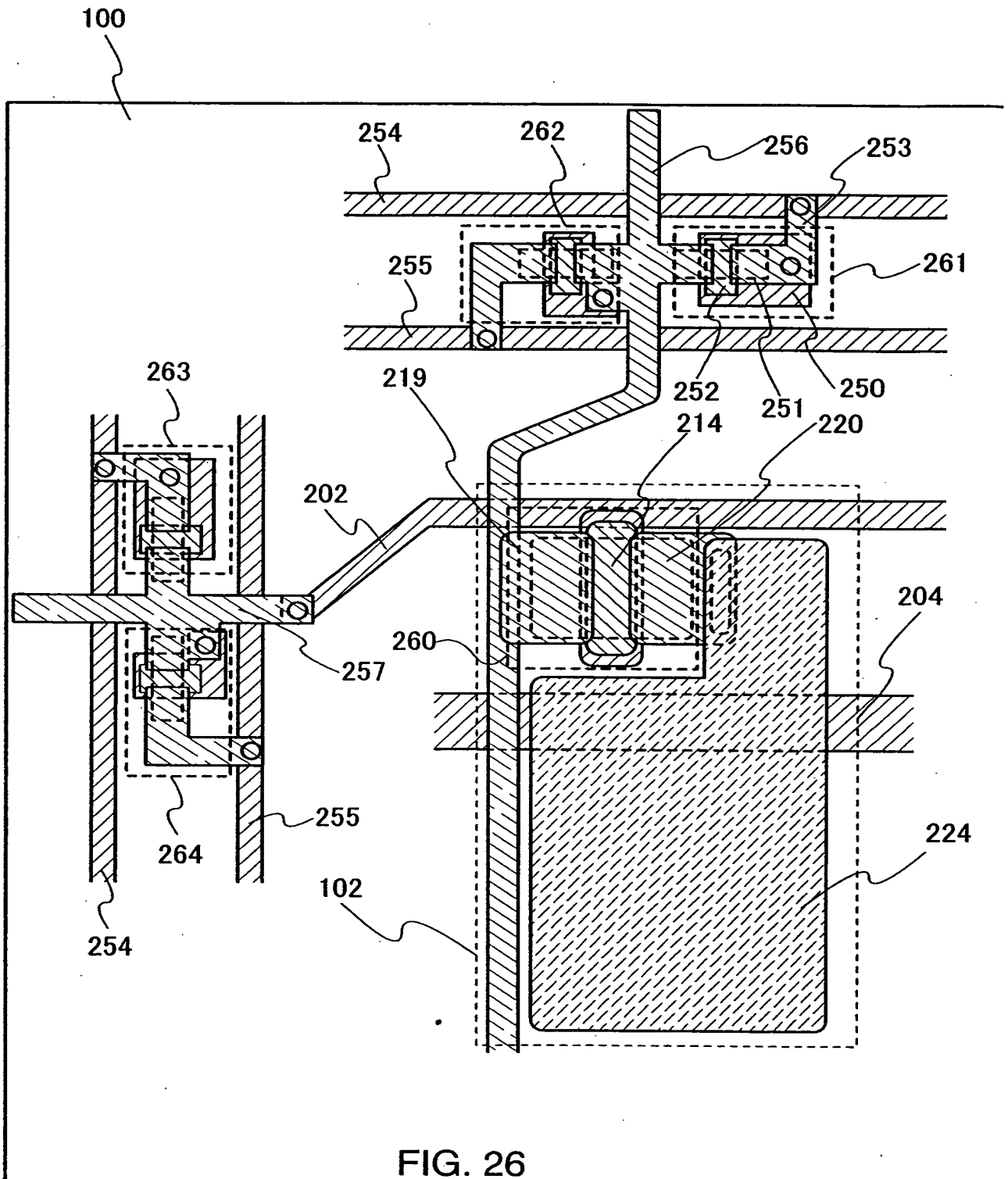


FIG. 25



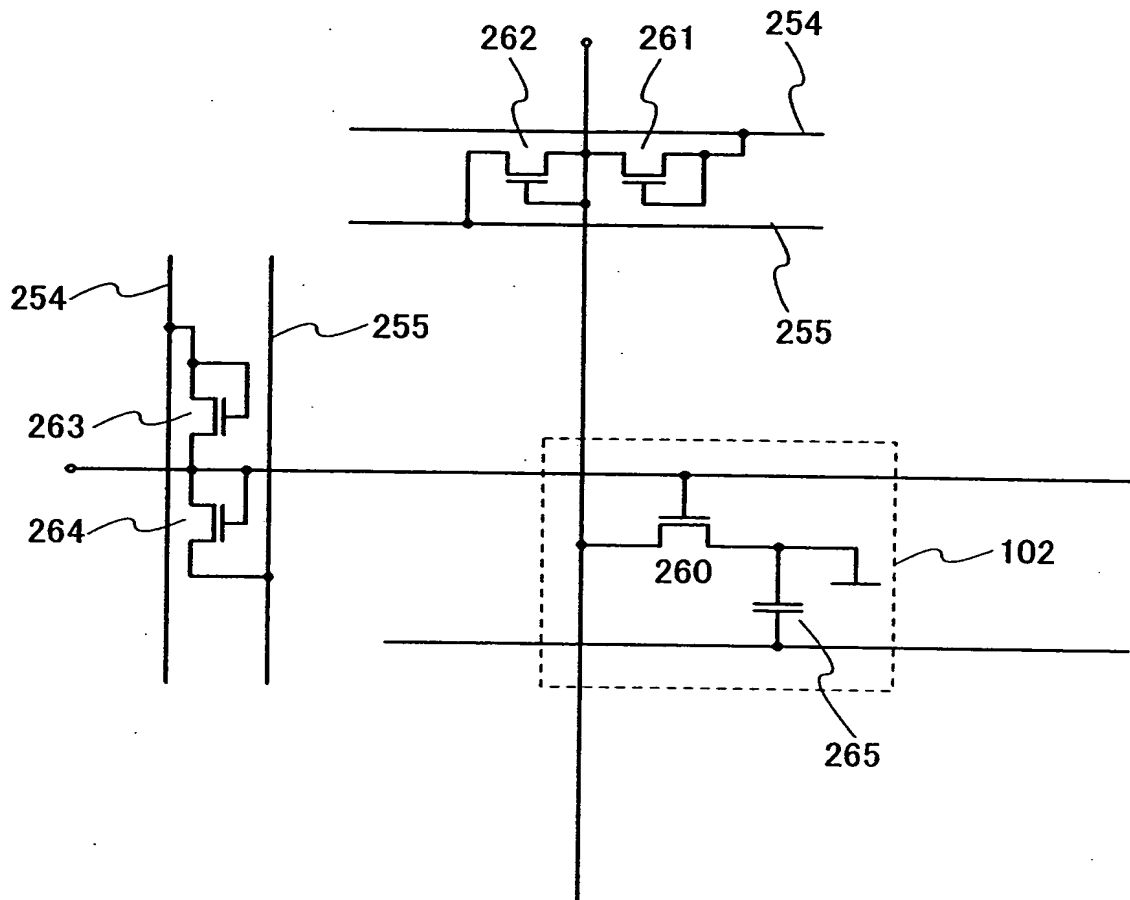


FIG. 27

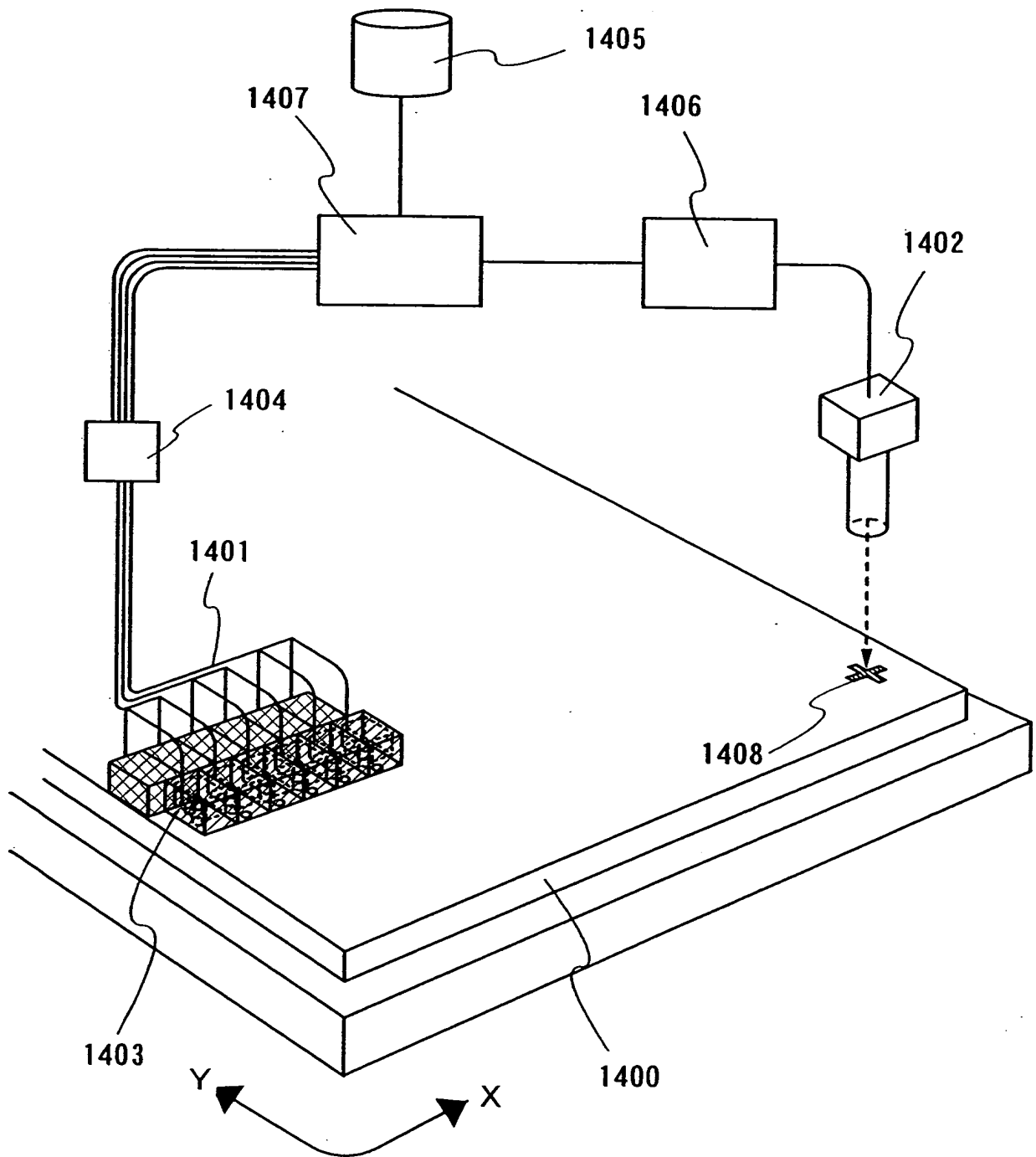


FIG. 28

FIG. 29A

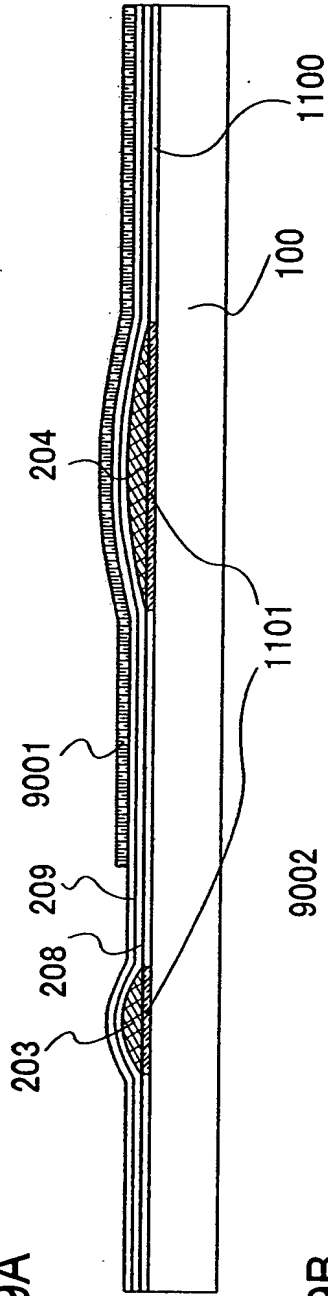


FIG. 29B

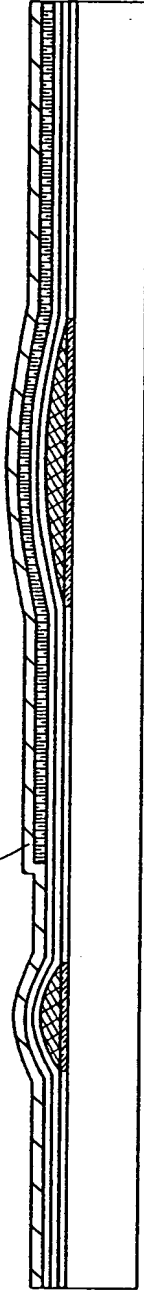


FIG. 29C

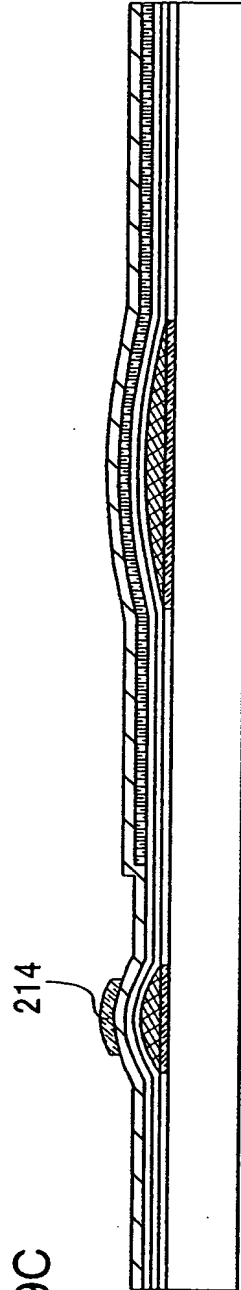
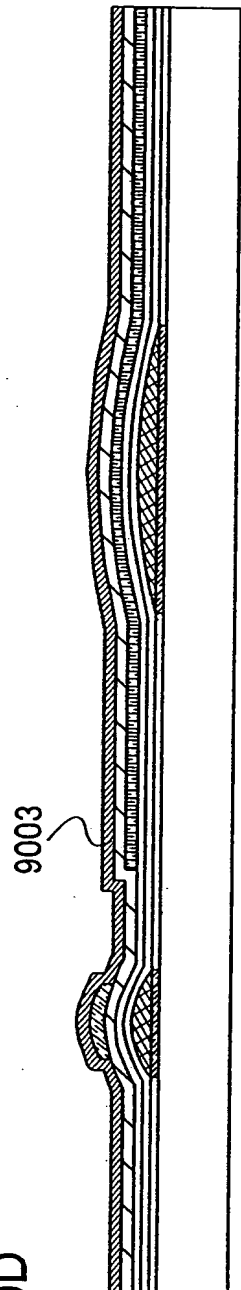
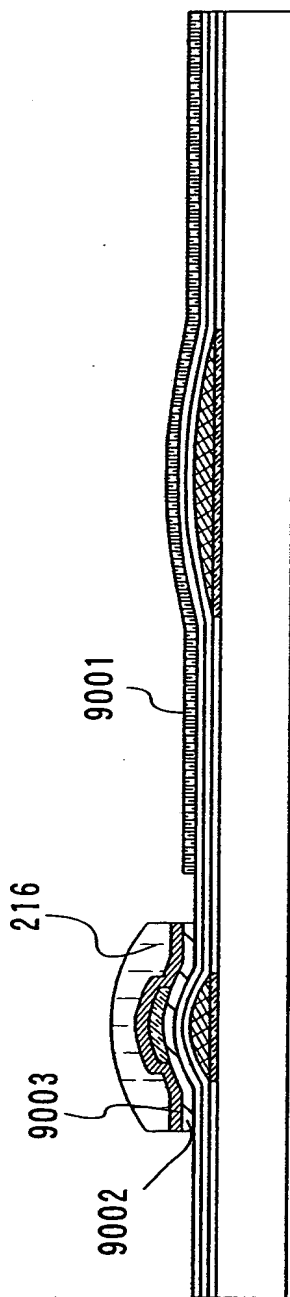


FIG. 29D



A cross-sectional view of a multi-layered structure. The structure consists of several layers: a top layer with diagonal hatching, a middle layer with a cross-hatch pattern, and a bottom layer with horizontal lines. A curved, dome-like feature labeled 216 is shown on the left side, protruding from the bottom layer and partially overlapping the middle layer. The feature 216 has a dashed line indicating its internal profile.



This cross-sectional view shows a multi-layered structure. At the bottom is a thick, hatched layer labeled 203. Above this is a thin layer labeled 9004. A wavy, irregular layer labeled 214 is situated above 9004. Above 214 is a thin layer labeled 9005. Above 9005 is a thin layer labeled 9003. The topmost layer is a thick, hatched layer labeled 204. The structure is shown between two vertical lines, with a dashed line on the left and a solid line on the right.

FIG. 32A

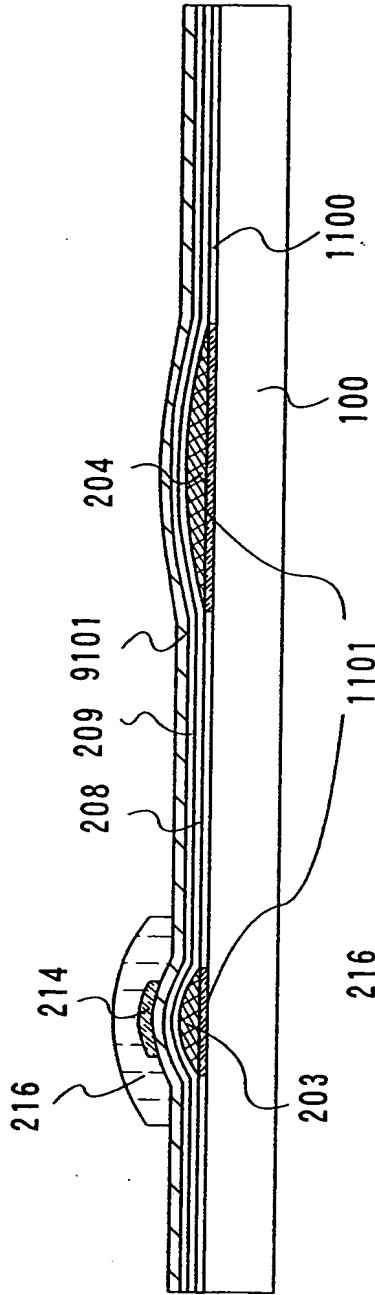


FIG. 32B

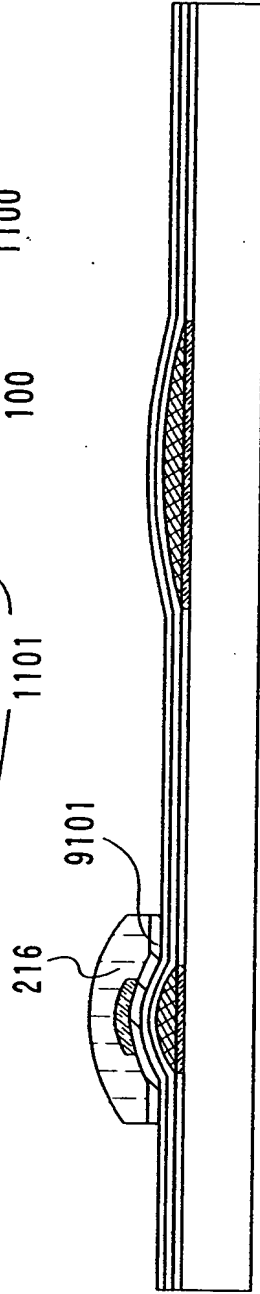


FIG. 32C

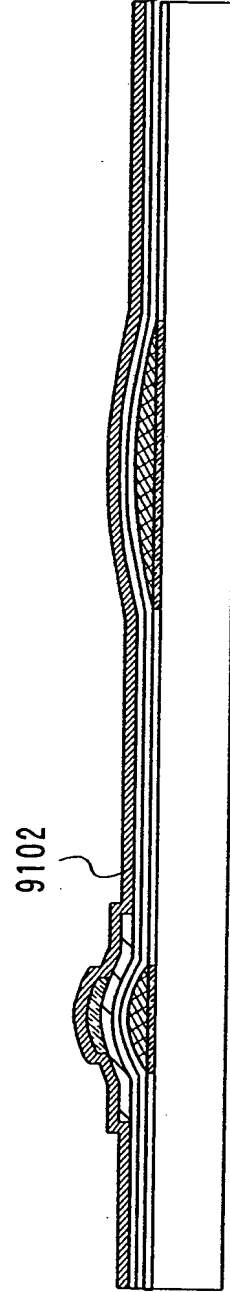


FIG. 32D

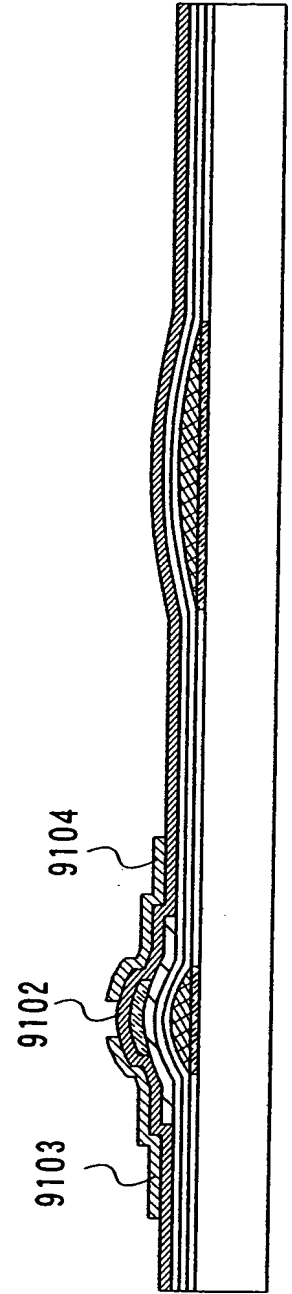


FIG. 33A

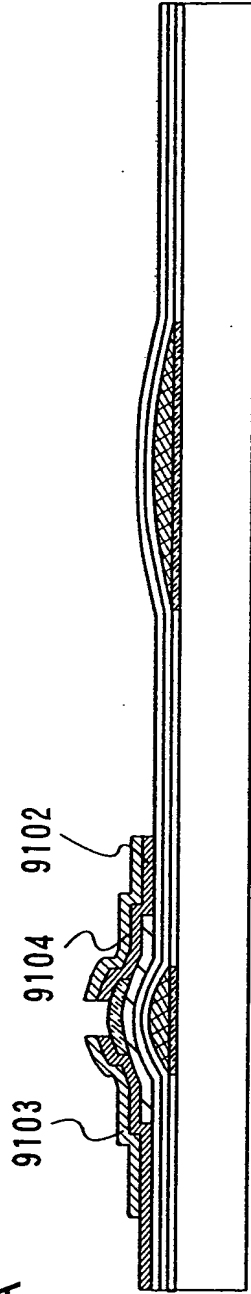


FIG. 33B

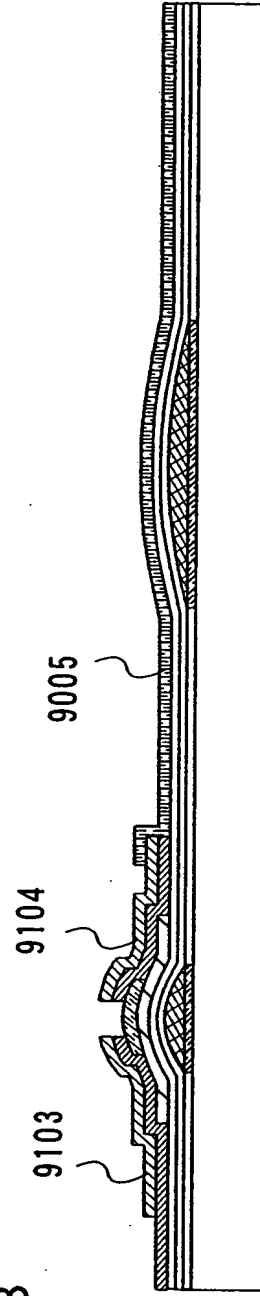


FIG. 34A

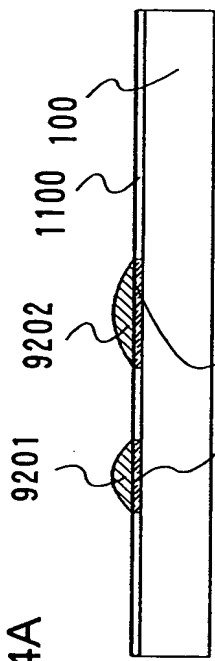


FIG. 34B

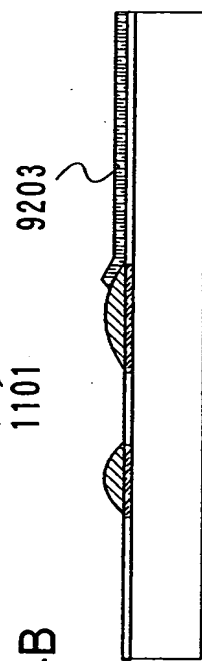


FIG. 34C

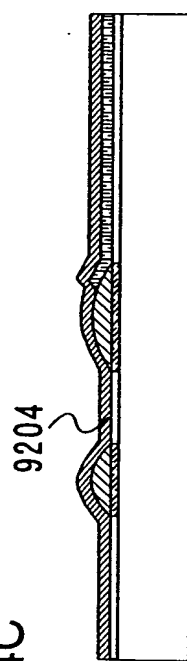


FIG. 34D

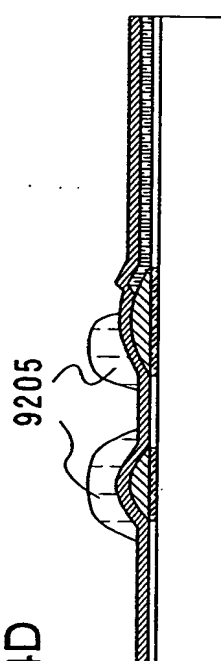


FIG. 34E

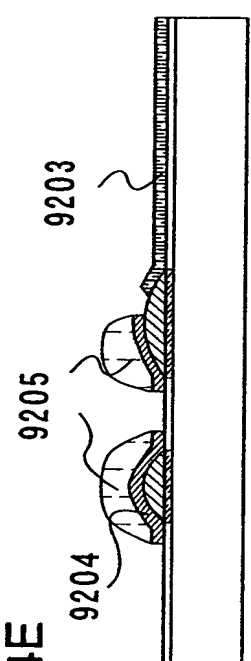


FIG. 34F

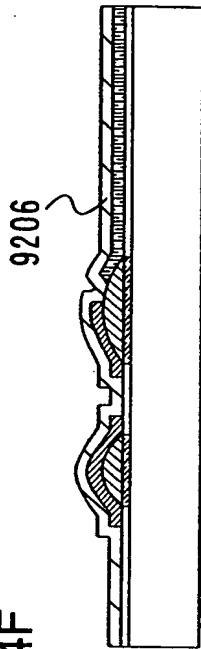


FIG. 34G

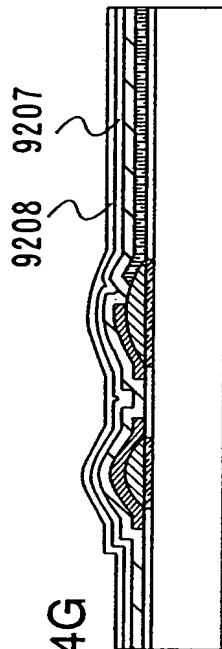


FIG. 34H

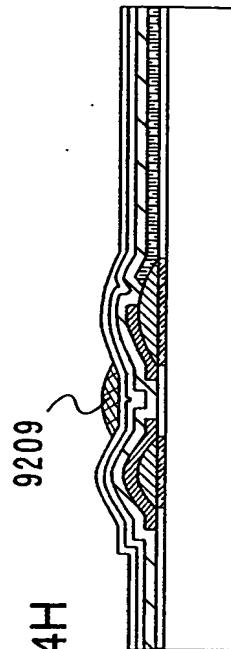


FIG. 34I

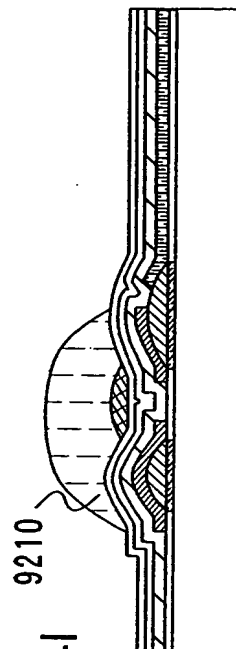
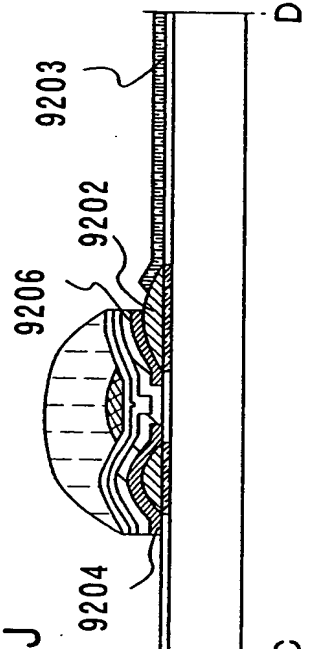
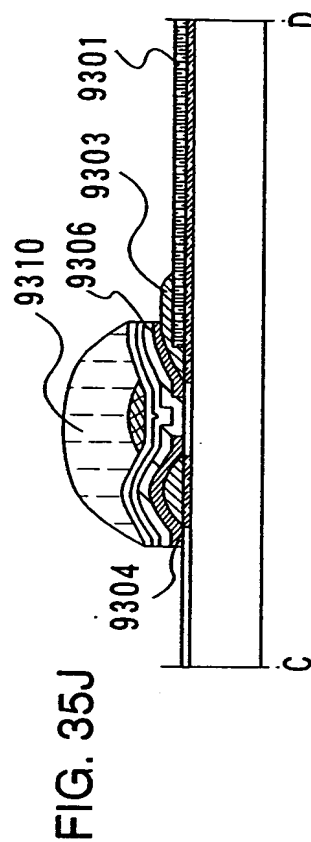
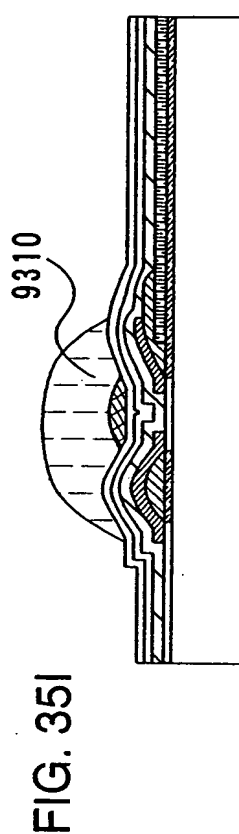
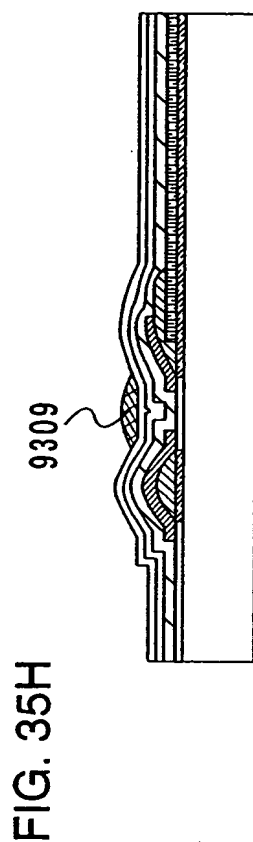
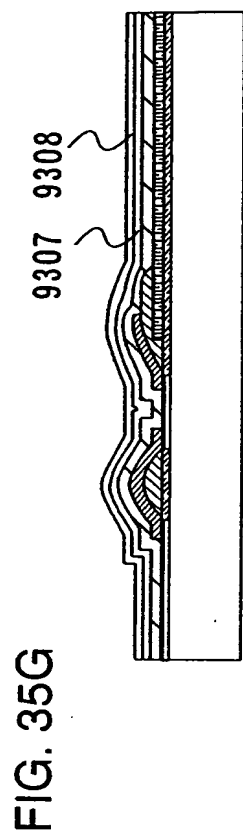
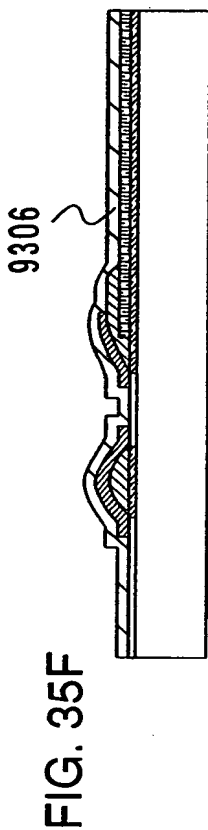
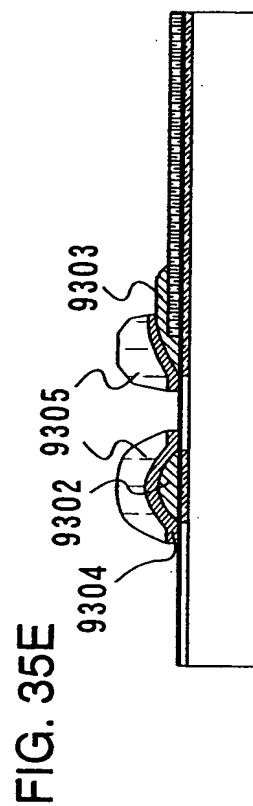
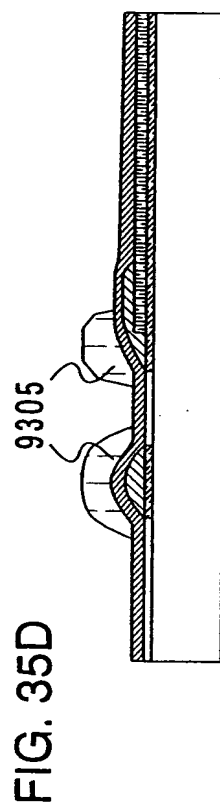
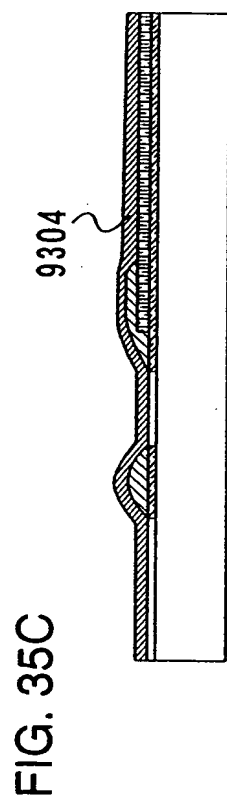
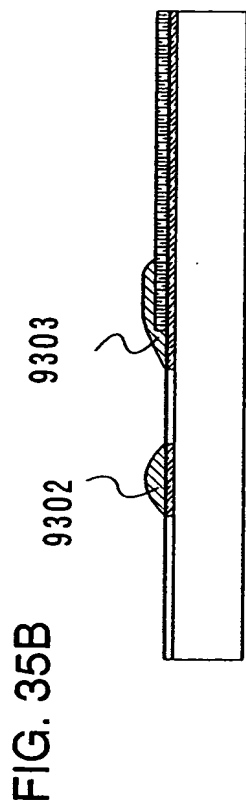
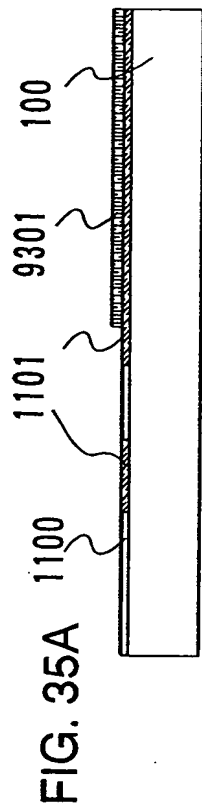


FIG. 34J





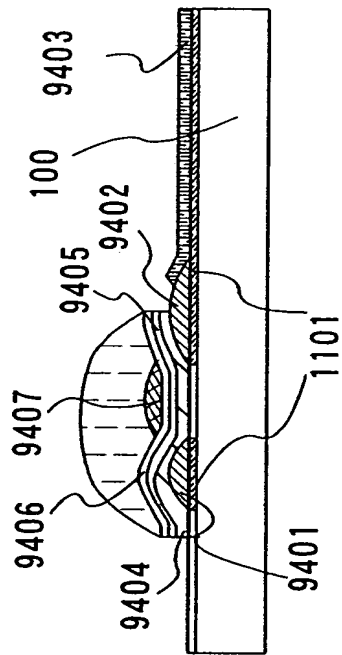


FIG. 36A

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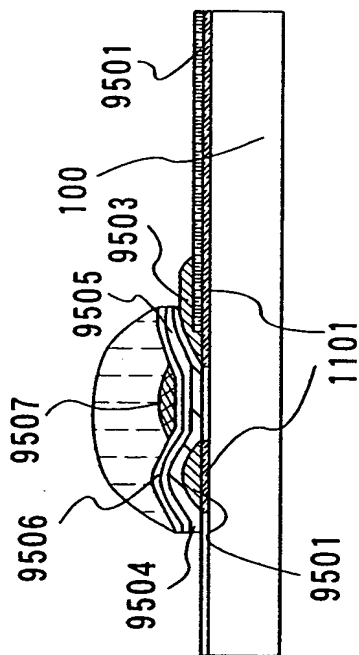


FIG. 36B



FIG. 37

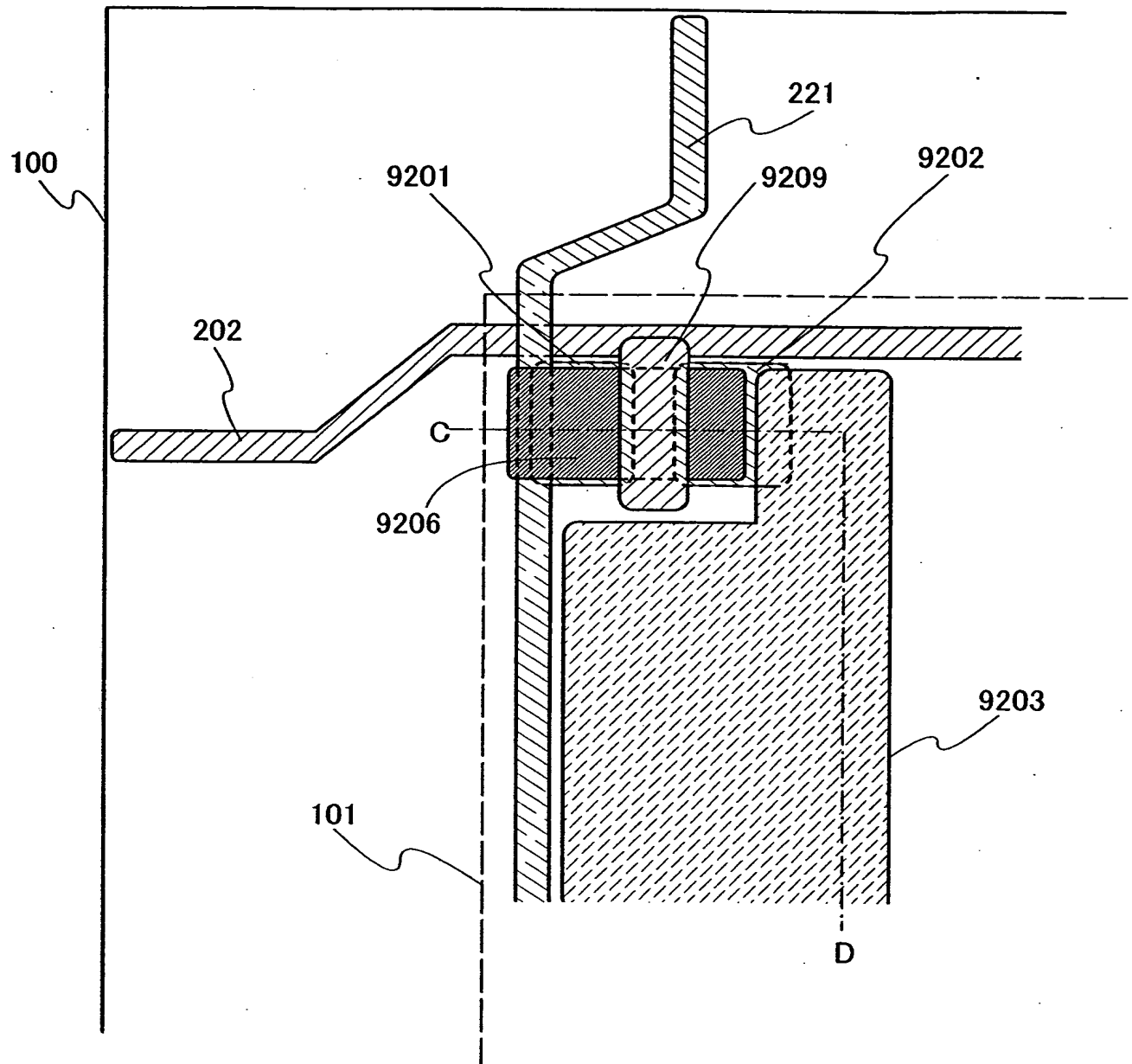


FIG. 38

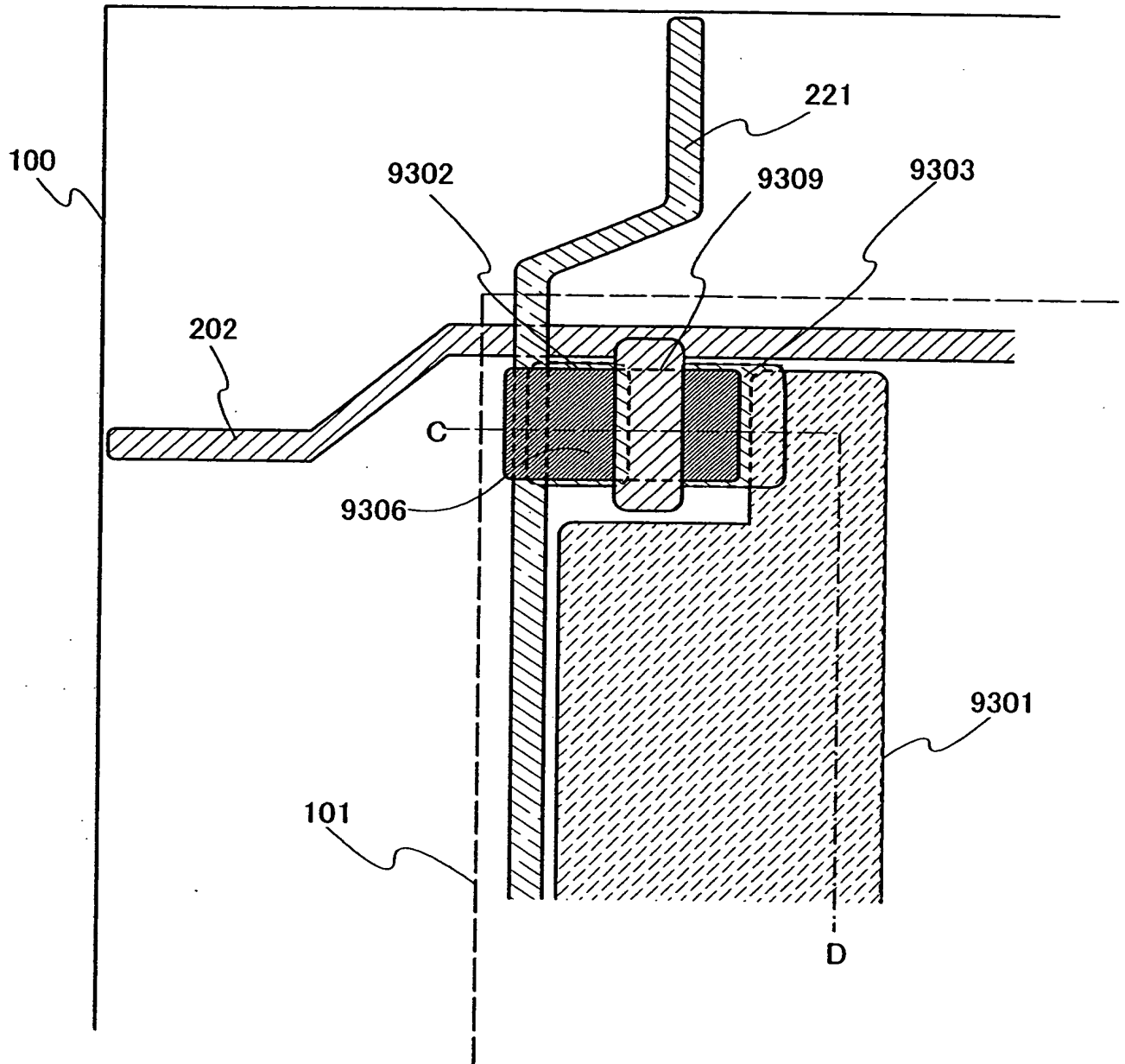


FIG. 39

EXPLANATION OF REFERENCE

100: substrate, 101: pixel portion, 102: pixel, 103: scanning line side input terminal, 104: signal line side input terminal, 105: driver IC, 106: driver IC, 107: scanning line side driver circuit, 108: protection diode, 201: signal wiring, 202: gate wiring layer, 203: gate electrode layer, 204: capacitor wiring layer, 205: TiO₂ layer, 206: TiO₂ layer, 207: TiO₂ layer, 208: insulating layer, 209: insulating layer, 210: insulating layer, 211: semiconductor layer, 212: insulating layer, 213: mask, 214: insulating layer, 216: mask, 217: semiconductor layer, 218: semiconductor layer, 219: source-drain wiring layer, 220: source-drain wiring layer, 221: signal wiring, 222: semiconductor layer, 223: semiconductor layer, 224: pixel electrode layer, 225: insulating layer, 226: sealant, 227: insulating layer, 228: conductive layer, 229: opposite substrate, 230: liquid crystal layer, 231: region, 232: wiring board, 233: switching TFT, 234: capacitor element, 235: connection wire layer, 240: insulating layer, 241: opening, 242: opening, 244 : insulating layer, 250: gate electrode layer, 251: semiconductor layer, 252: insulating layer, 253: wiring layer, 254: common potential line, 255: common potential line, 256: signal wiring layer, 259: light conducting plate, 260: TFT, 261: protection diode, 262: protection diode, 263: protection diode, 264: protection diode, 265: capacitor element, 270: colored layer, 271: polarizing plate, 272: polarizing plate, 273: flexible wiring board, 274: circuit board, 275: cold cathode fluorescent tube, 301: semiconductor layer, 302: mask, 303: semiconductor layer, 304: semiconductor layer, 305: source-drain wiring layer, 306: source-drain wiring layer, 307: semiconductor layer, 308: semiconductor layer, 309: semiconductor layer, 310: pixel electrode layer, 311: insulating layer, 312: sealant, 313: orientation film, 314: opposite electrode, 315: substrate, 316: liquid crystal layer, 317: connection terminal, 401: pixel portion, 402: signal line side driver circuit, 403: scanning line side driver circuit, 404: tuner, 405: video signal amplifier circuit, 406: video signal processing circuit, 407: control circuit, 408: signal dividing circuit, 409: audio signal amplifier circuit, 410: audio signal processing circuit, 411: control circuit, 412: input portion, 413: speaker, 500: pulse output circuit, 501: buffer circuit 502: pixel, 601 to 635: TFT, 811: resin, 812: FPC, 813: wiring, 814: conductive particle, 815: resin, 816: adhesive, 817: wiring, 818: sealing resin, 1001: substrate, 1002: pixel portion, 1003: driver circuit, 1004: driver circuit, 1005: substrate, 1006: tape, 1007: IC chip, 1008: substrate, 1009: tape, 1010: IC chip, 1100: Ti film, 1101: activation region, 1201: connection wiring layer, 1202: connection wiring layer, 1203: connection wiring layer, 1400: substrate, 1401: droplet discharge means, 1402: imaging means, 1403: head, 1404: control means, 1405: storage medium,

1406: image processing means, 1407: computer, 1408: marker, 2301: module chassis, 2302: speaker, 2303: display screen, 2304: speaker, 2305: operation switch, 9001: pixel electrode, 9002: semiconductor layer, 9003: semiconductor layer, 9004: source-drain wiring layer, 9005: source-drain wiring layer, 9101: semiconductor layer, 9102: semiconductor layer, 9103: source-drain wiring, 9104: source-drain wiring, 9105: pixel electrode, 9201: source-drain wiring layer, 9202: source-drain wiring layer, 9203: pixel electrode, 9204: semiconductor layer, 9205: mask, 9206: semiconductor layer, 9207: gate insulating film, 9208: gate insulating film, 9209: pixel electrode, 9210: mask, 9301: pixel electrode, 9302: source-drain wiring layer, 9303: source-drain wiring layer, 9304: semiconductor layer, 9305: mask, 9306: semiconductor layer, 9307: gate insulating film, 9308: gate insulating film, 9309: gate electrode, 9310: mask